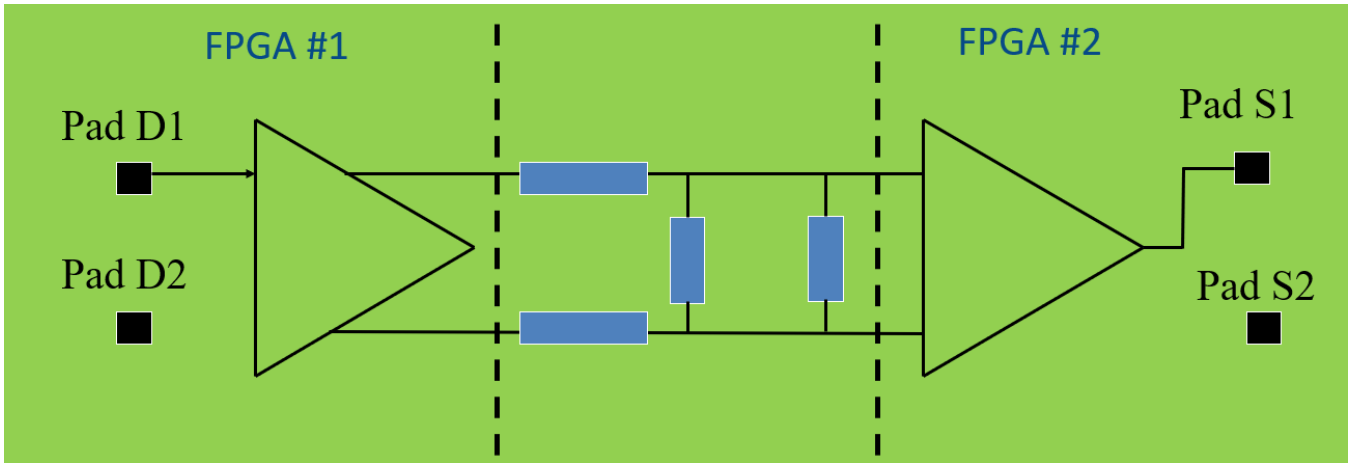
Guidelines for Board Design for Test (DFT) based on Boundary Scan

Volume 2



Michael R. Johnson – Product Manager

Michael R. Johnson serves as Product Manager for ScanWorks Boundary Scan Test (BST) for ASSET InterTech, Inc. He also serves as manager of ASSET's Application Engineering and Professional Services organization. As Product Manager, Michael provides strategic direction for the ScanWorks BST product, ensuring an exceptional customer experience and adherence to current and future IEEE standards requirements. Michael coordinates with ASSET's cross-functional teams such as Marketing, Sales, Support, and Research and Development, to bring ASSET's business goals to fruition.

Before ASSET, Michael's background included roles as a Cellular System Engineer with Nortel Networks and a Hardware Design Engineer with Alcatel USA. While at Nortel Networks, Michael analyzed and provided handoff measurement data for Nortel's mobile and Personal Communications Services (PCS) networks. As a Hardware Design Engineer, Michael designed printed circuit board modules capable of transmitting and receiving optical signals at 622.08 Mbits/s for Alcatel's transport fiber-optic systems.

Michael earned a Bachelor of Science degree with honors in Electrical Engineering from Southern University and A&M College located in Baton Rouge, Louisiana, and a Master of Business Administration degree with an emphasis in Strategic Leadership from Amberton University located in Garland, Texas.

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Executive Summary

In this eBook, we will examine Design for Test (DFT) guidelines specific to the design of boards to be tested through the Boundary Scan registers of IEEE 1149.1-compliant devices. Implementing Boundary Scan DFT guidelines adds the unique capability of accessing onboard test resources for a non-intrusive test which provides open and short faults coverage. Following DFT guidelines during the board design process makes the board easier to test for defects. DFT guidelines provide an opportunity to increase boar test coverage. As boards move through the manufacturing process, the goal is to reduce the number of defective boards produced. Defects need to be identified quickly so they can be repaired, and processes can be adjusted. Boundary Scan can also be used to test memory devices and for configuration of programmable logic devices (PLD) and flash memory devices. The DFT guidelines contained herein have been assembled over many years of experience by the technical staff of ASSET InterTech and validated across a variety of simple and complex board designs. Volume 2 of this eBook will specifically address DFT guidelines related to interconnect testing, memory interconnect testing, flash programming, and testing with Field Programmable Gate Array (FPGA) devices.

Figure 1: Board DFT based on Boundary Scan – Agenda

Board Level Design for Test (DFT) Guidelines – Volume 1

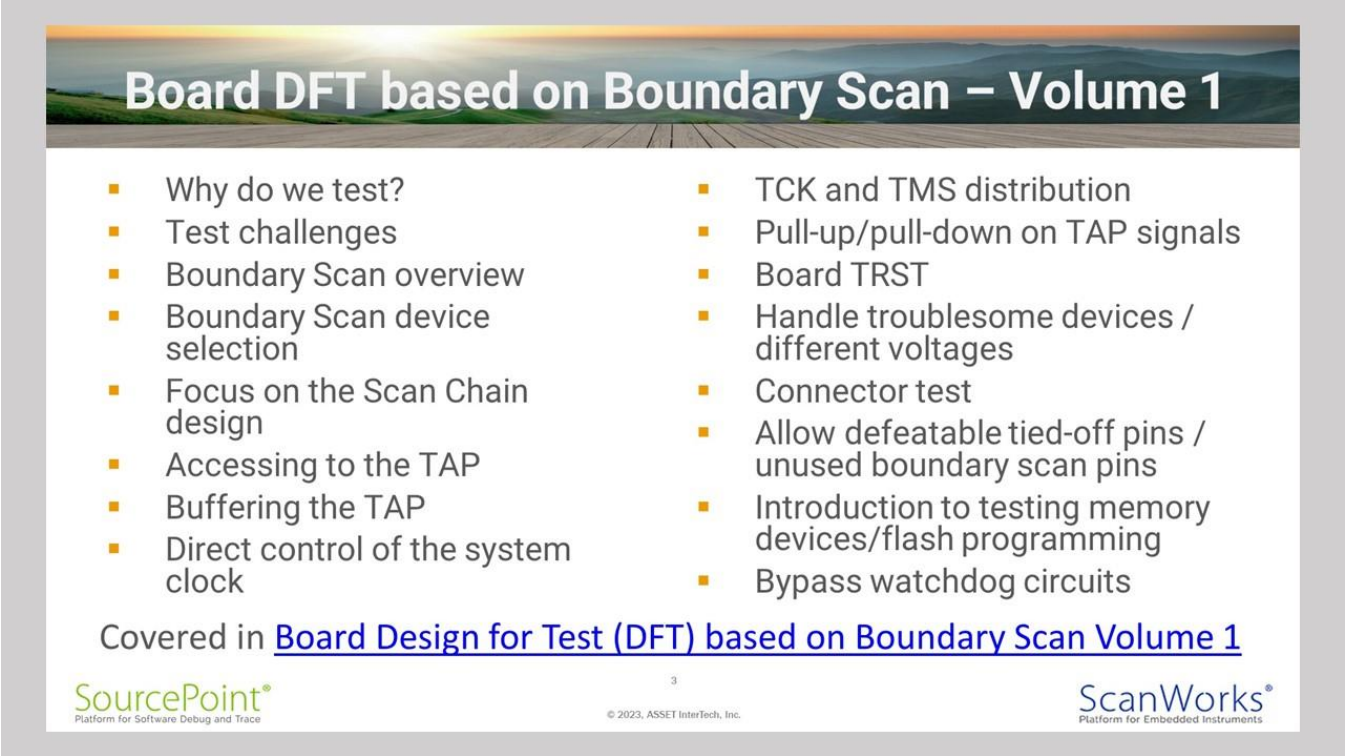

Figure 2: Board DFT based on Boundary Scan – Volume 1

These DFT guidelines were covered in volume 1 of this DFT eBook which can be downloaded from the ASSET website.

Interconnect Testing with Boundary Scan

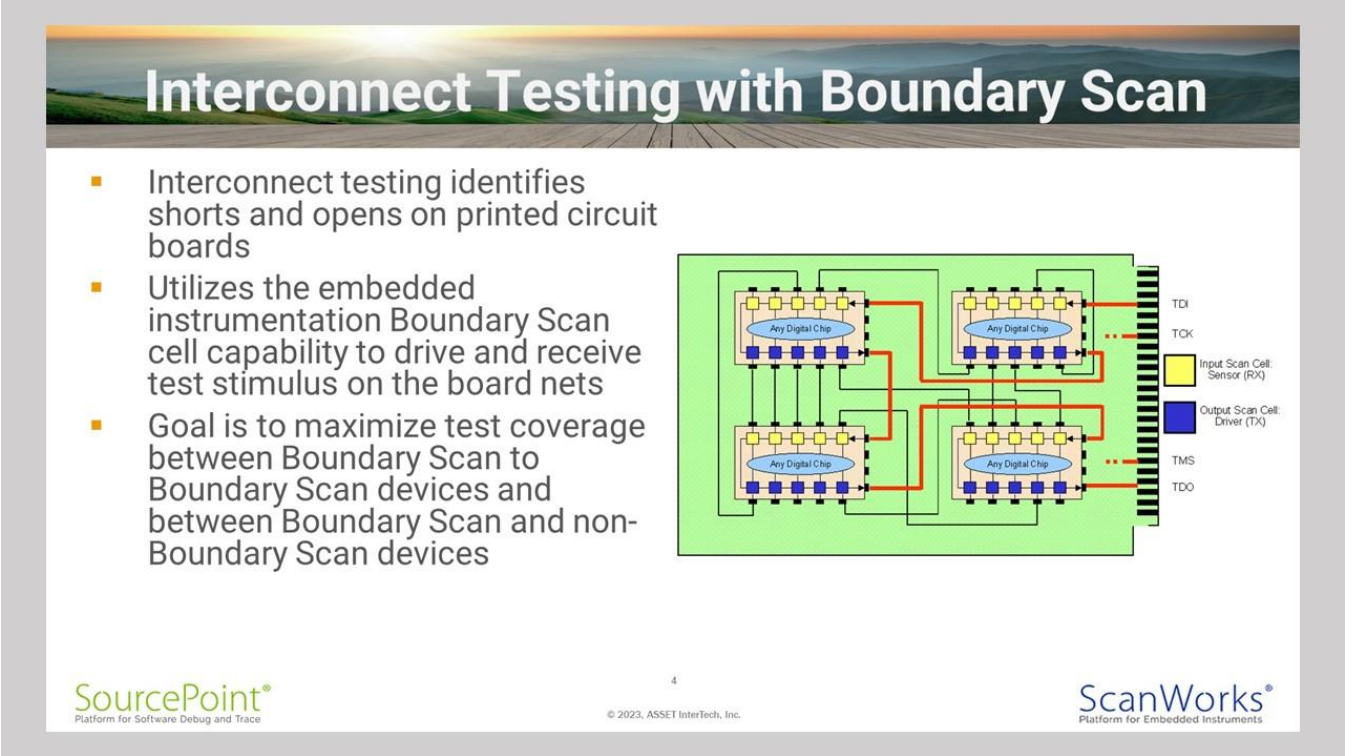

Figure 3: Interconnect Testing with Boundary Scan

Our goal when testing interconnects is to maximize board test coverage. We want to maximize the number of opens and shorts detected with the set of test patterns generated. One obstacle to board test coverage is non-Boundary Scan devices driving signals onto Boundary Scan nets. Increasing board test coverage is the first DFT guideline we will examine.

Interconnect Testing with Boundary Scan – Chip Enables

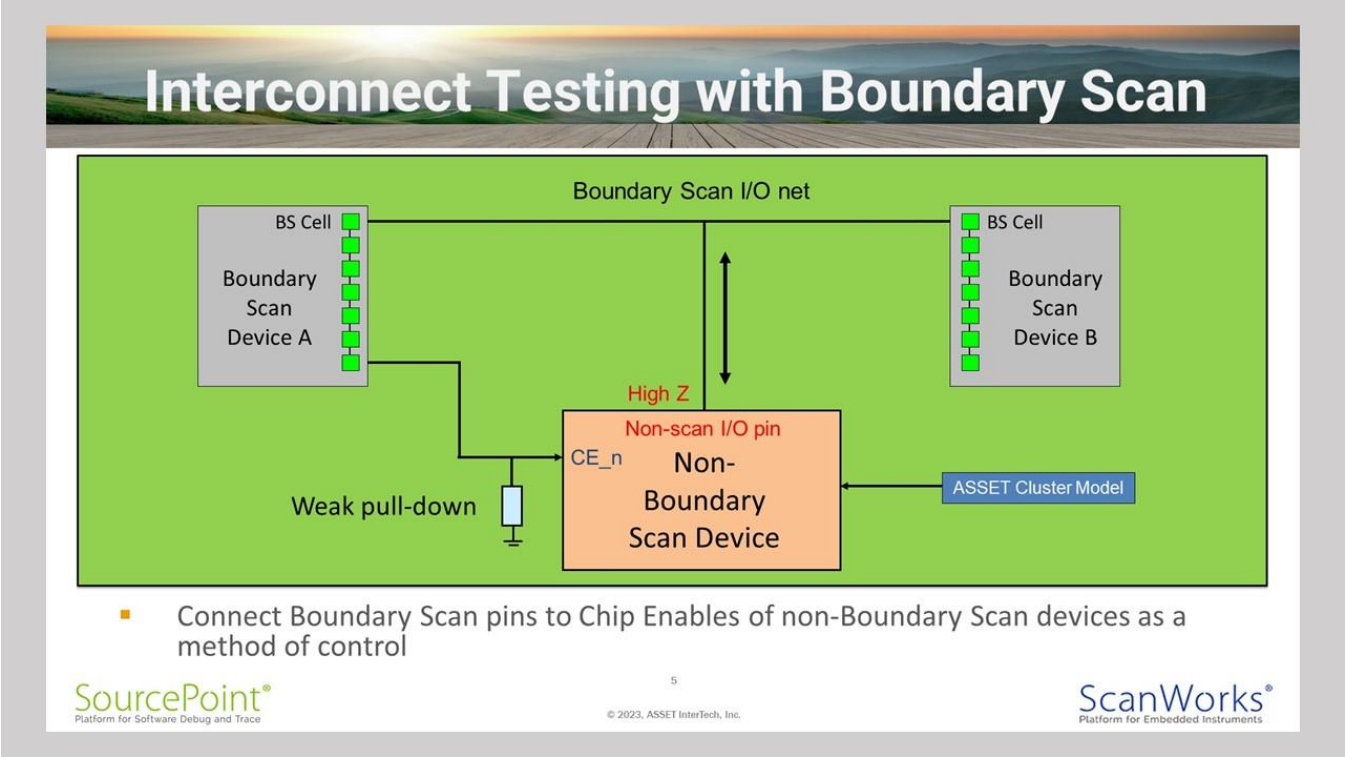

Figure 4: Interconnect Testing with Boundary Scan – Chip Enables

In this scenario, we have a Boundary Scan I/O net connected between device A and device B. Assuming the Boundary Scan pins are bi-directional I/O, a stimulus can be driven from device A to device B then from device B to device A. However, when a non-Boundary Scan device drives signals onto the net, the entire net will not be driven by ScanWorks unless it knows it is safe to do so. To supply this information to ScanWorks, we apply a cluster model to the non-Boundary Scan device. The cluster model describes the I/O characteristics of the device. It also tells ScanWorks how to disable the I/O via the Chip Enable pin so it can be driven safely.

Following the DFT guideline of connecting Boundary Scan pins to Chip Enables of Non-Boundary Scan devices serves as a method of control. We want to disable the outputs of as many of these devices as possible and force the outputs to a high-impedance state.

Not disabling the non-Boundary Scan device could lead to false fails due to outputs from the non-Boundary Scan device corrupting the test signals or it could cause damage as we back-drive into output amplifiers.

Interconnect Testing with Boundary Scan – Cluster Model

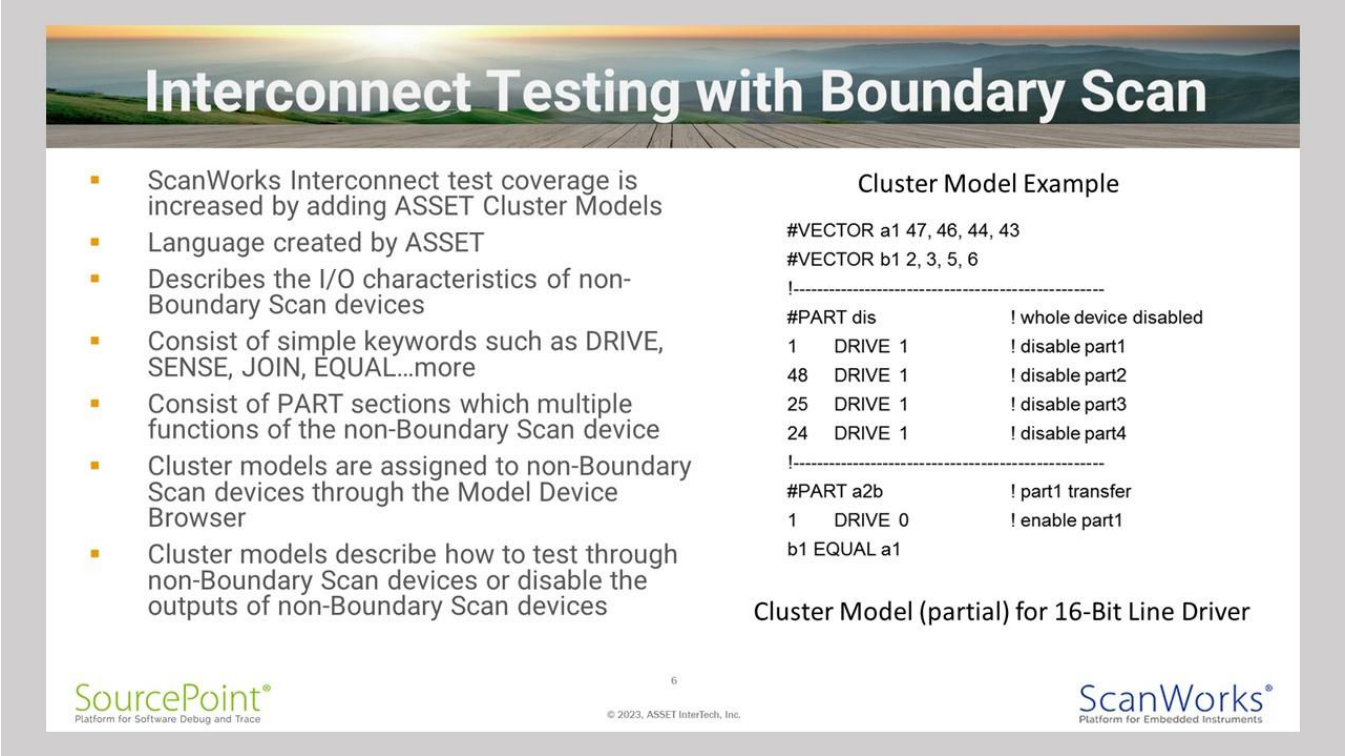

Figure 5: Interconnect Testing with Boundary Scan – Cluster Model

This is an example of an ASSET Cluster model. Cluster models describe the I/O characteristics of non-Boundary Scan devices. Cluster models also can describe how to test through non-Boundary Scan devices. For more information on cluster models, you can refer to the document “bscaninterconnect.pdf” located in the C:\ScanWorks\Doc directory.

Interconnect Testing with Boundary Scan – Discrete I/O

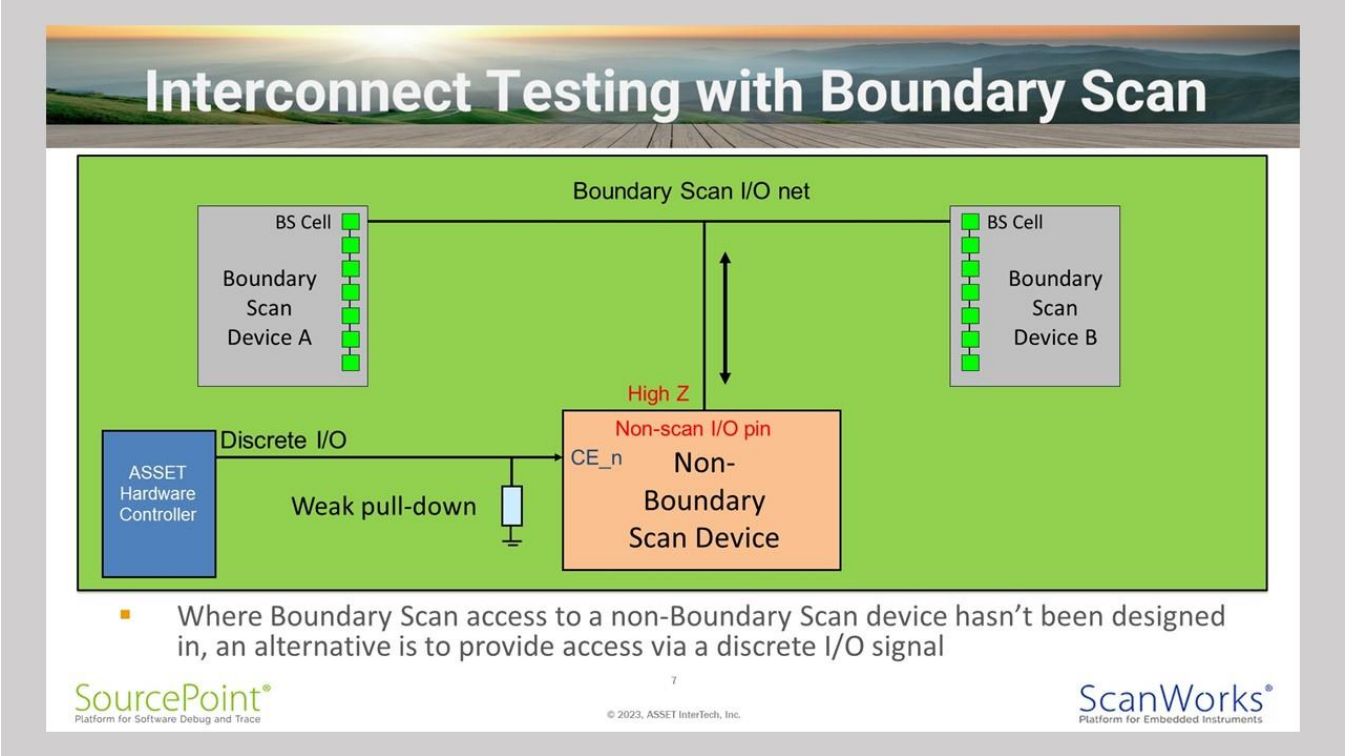

Figure 6: Interconnect Testing with Boundary Scan – Discrete I/O

Where Boundary Scan access to a non-Boundary Scan device's Chip Enable has not been designed in via a Boundary Scan pin, an alternative is to provide direct access via a discrete I/O signal. ASSET hardware controllers can control pins independent of the test bus.

Discrete I/O actions can be created to drive pins of non-Boundary Scan devices. In this scenario, a Discrete I/O action can be created to drive the Chip Enable to disable the non-Boundary Scan device outputs.

Interconnect Testing with Boundary Scan – Output Enables

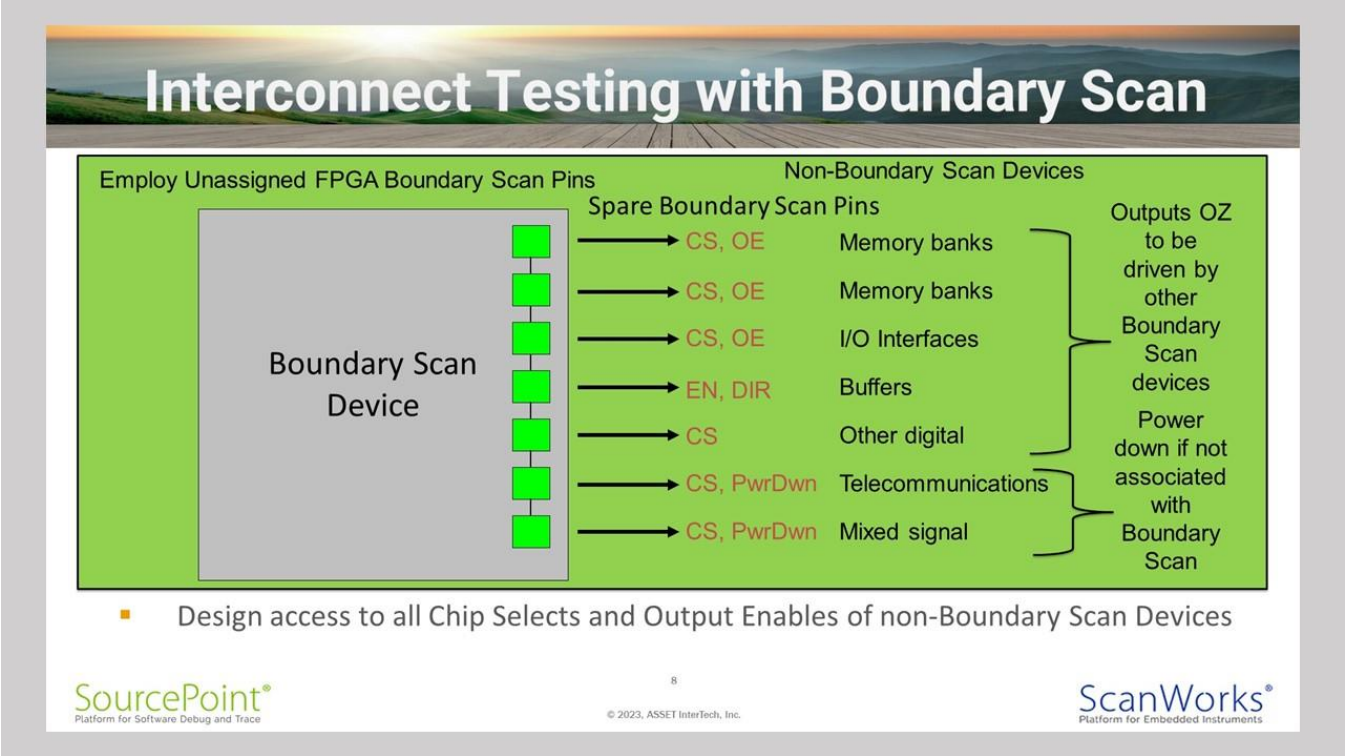

Figure 7: Interconnect Testing with Boundary Scan – Output Enables

Unassigned FPGA pins can be used for disabling non-scan Boundary Scan devices. Unassigned FPGA pins are normally floating when the system is functioning in the field. However, Boundary Scan can still access and drive these pins during tests.

With bi-directional buffers devices, it can be useful to control the direction. Maybe some nets are tested in one direction and some in the other. Some devices do not have a Chip Select but they do have a power-down Chip Enable pin that tri-states all outputs. The ability to selectively disable devices can be extremely useful during prototype testing.

Interconnect Testing with Boundary Scan – Controlling Clocks

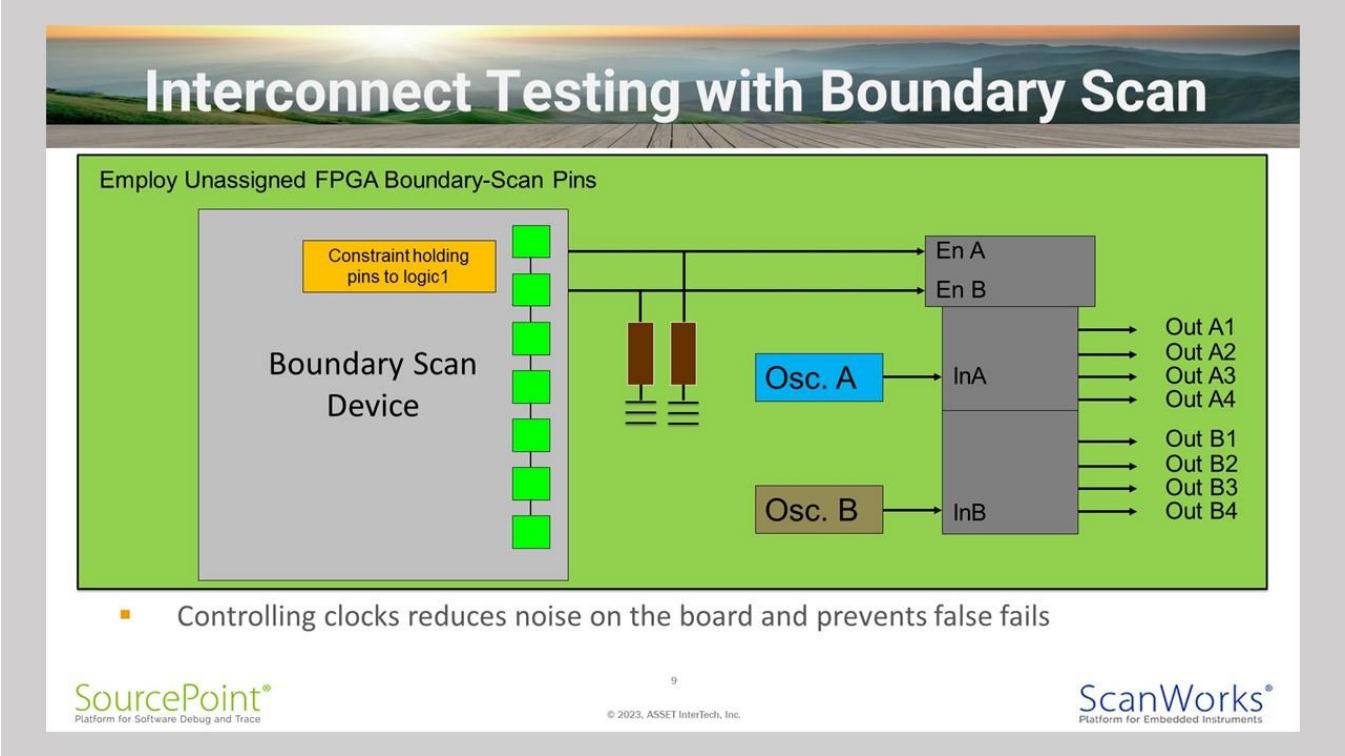

Figure 8: Interconnect Testing with Boundary Scan – Controlling Clocks

By controlling clocks, we can reduce noise on the board. Noise can cause false fails on tests. The ability to selectively disable clocks can be extremely useful during prototype testing.

The clock outputs could be disabled by using a ScanWorks constraint on Enable A and/or Enable B. With a constraint, a Boundary Scan pin can be held to a specific level, in this case, a logic 1, throughout the interconnect test.

Interconnect Testing with Boundary Scan – Connectors

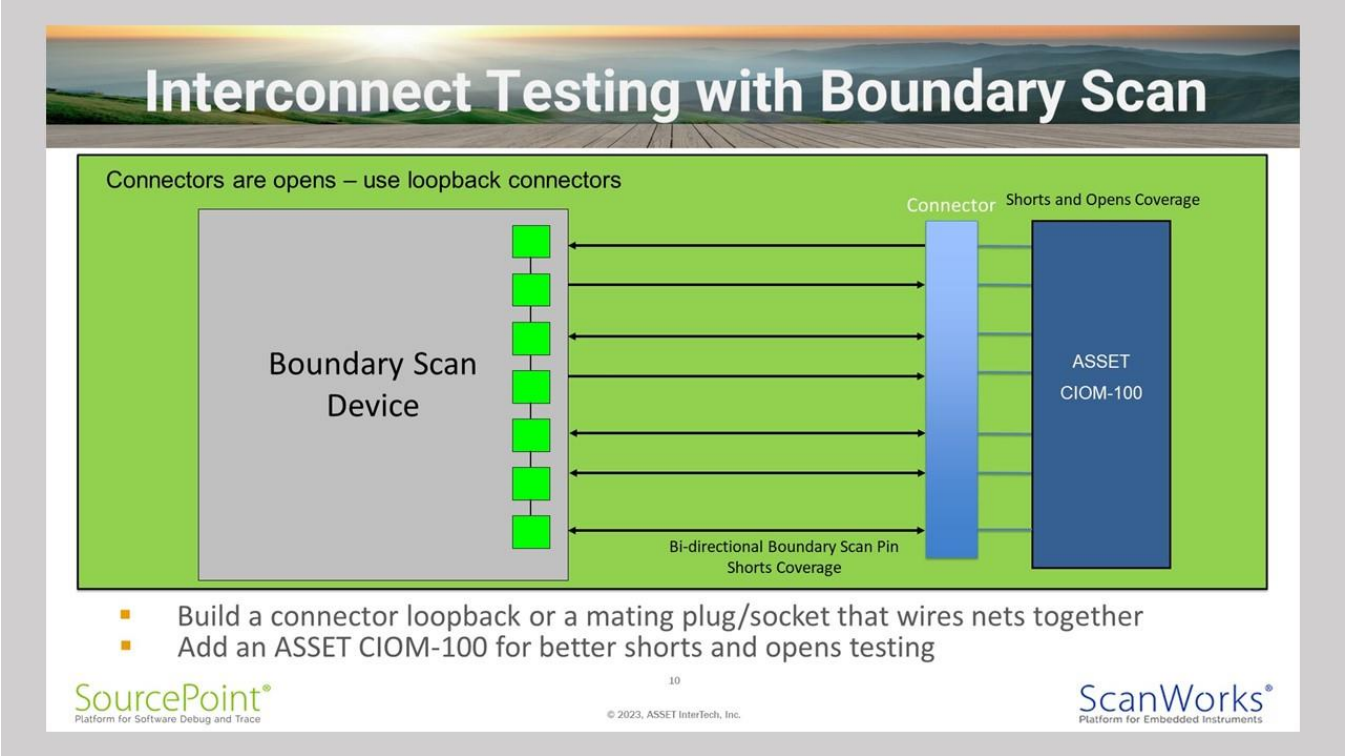

Figure 9: Interconnect Testing with Boundary Scan - Connectors

When nets are routed from a Boundary Scan device to a connector, we cannot test for opens (assuming no pull-up or pull-down resistor on net). In effect, the net is already an open.

A solution is to build a connector loopback, a mating plug/socket that wires nets together during the interconnect tests. The Boundary Scan test drives test signals out on one pin and senses them on one or more other pins. Opens will be detected if the driven pattern is not received.

For the net that does not have a loopback, if the pin is bi-directional, ScanWorks will drive the net and sense the input for shorts. Another way to test through a connector is to utilize a Boundary Scan device. ASSET has a configurable module with 100 I/O that is suited for this purpose.

Memory Interconnect Testing with Boundary Scan

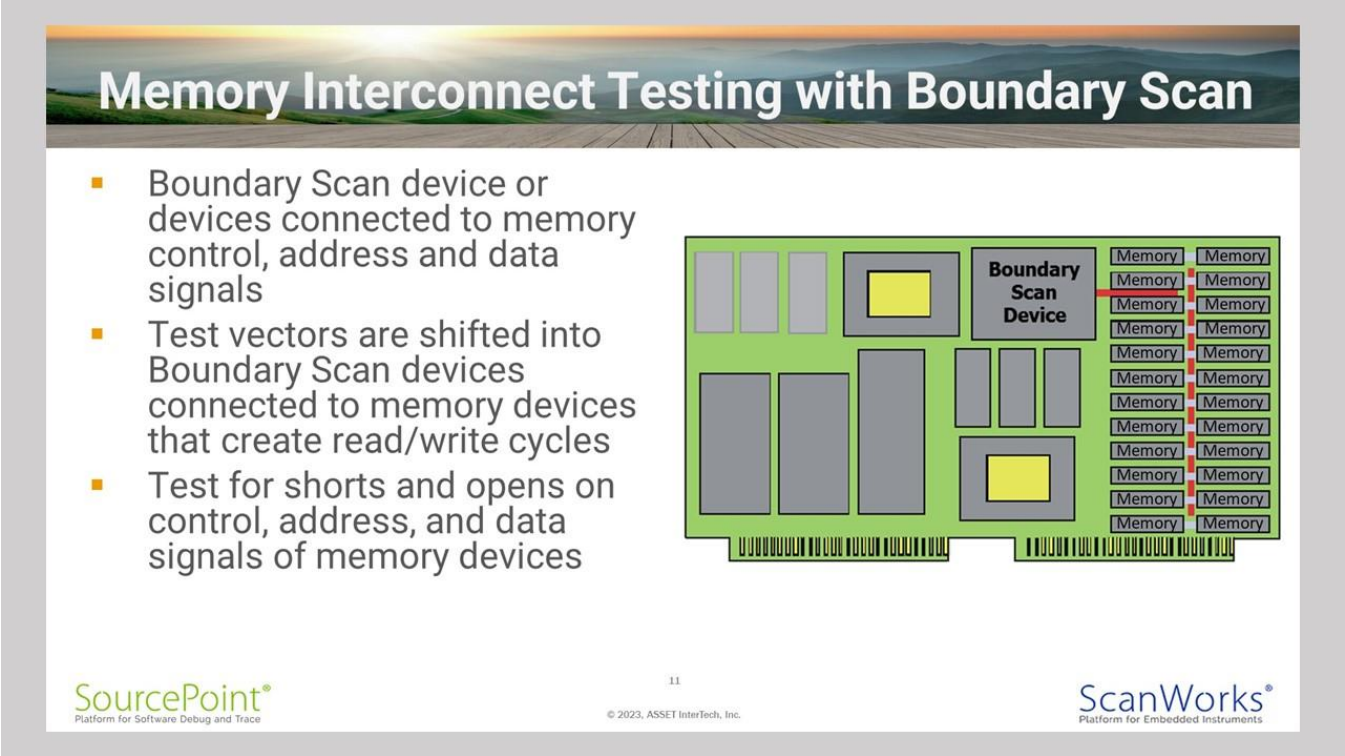

Figure 10: Memory Interconnect Testing with Boundary Scan

Memory devices rarely have Boundary Scan cells. For memory interconnect testing, test patterns are written into memory and then read back from the memory. If the patterns read back match the patterns written, the signals to the memory are structurally intact.

Memory Interconnect Testing with Boundary Scan – Chip Enables

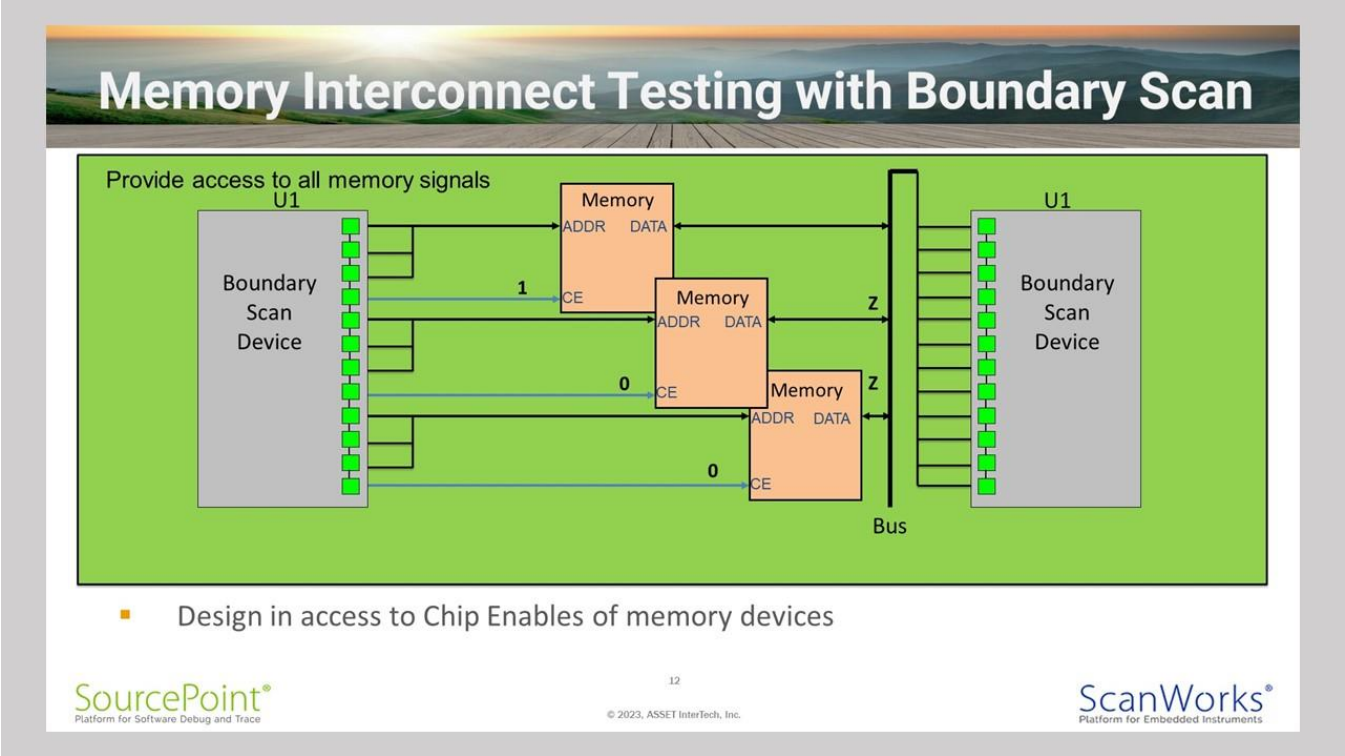

Figure 11: Memory Interconnect Testing with Boundary Scan – Chip Enables

For Boundary Scan memory interconnect testing, Boundary Scan access is needed to all address, data, and control pins. Access should come from the same Boundary Scan device in the same chain.

When testing memory banks, follow the DFT guideline of connecting Boundary Scan pins to Chip Enables of memory devices as a method of control. We want to disable the outputs (the data bus) to prevent false interconnect fails and contention.

Programming Flash Memory with Boundary Scan

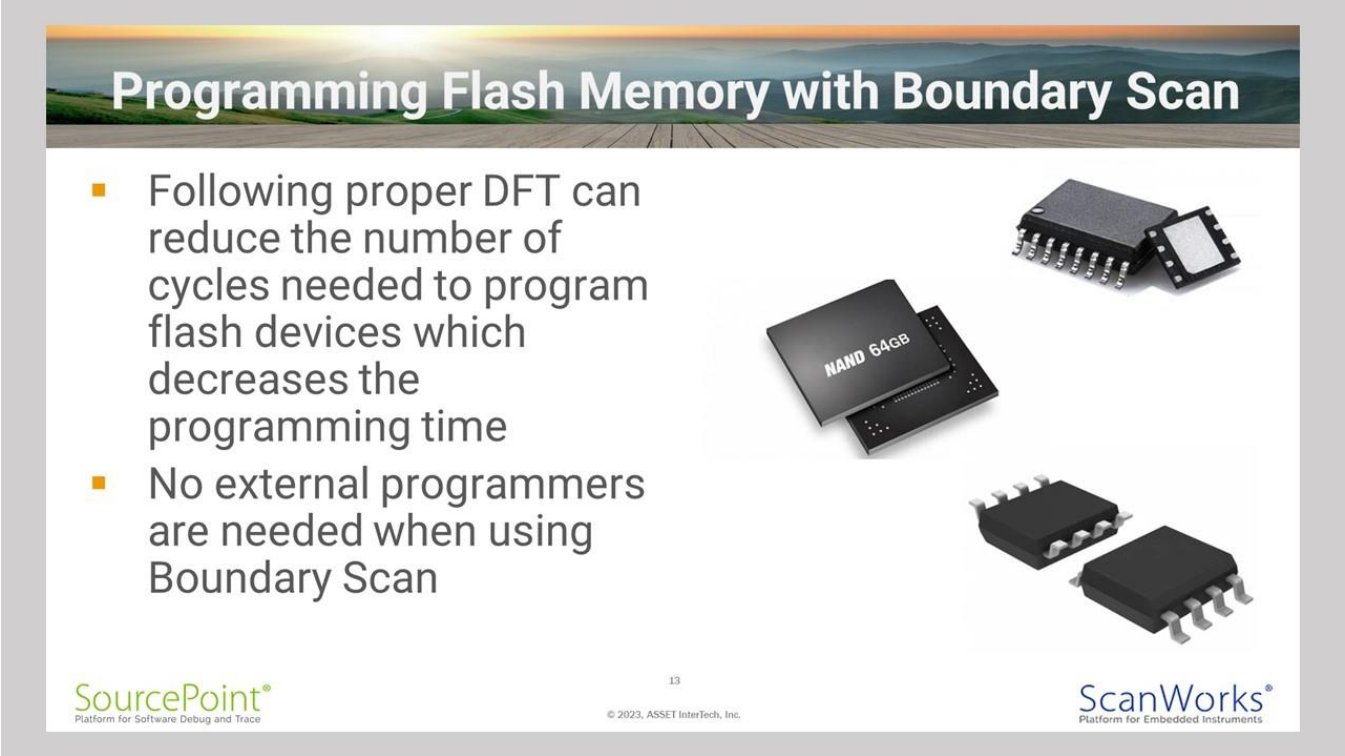

Figure 12: Programming Flash Memory with Boundary Scan

The time involved in programming a flash device through Boundary Scan can range from minutes to hours. This range in programming times can depend on following appropriate DFT guidelines for flash devices.

Programming Flash Memory with Boundary Scan – All Access

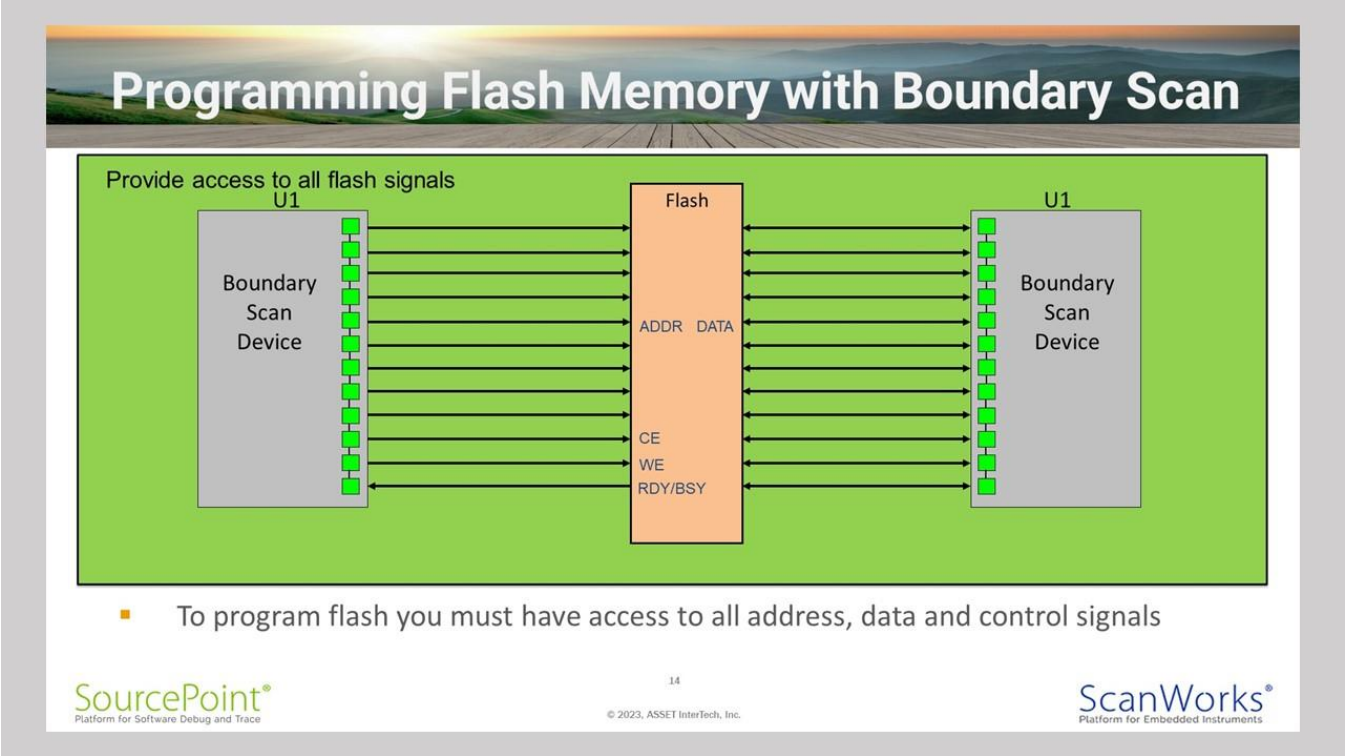

Figure 13: Programming Flash Memory with Boundary Scan – All Access

To program flash, you must have access to all address, data, and control signals and it is best, from a DFT perspective, that all access comes from the same Boundary Scan device.

Programming Flash Memory with Boundary Scan – External Cell Active

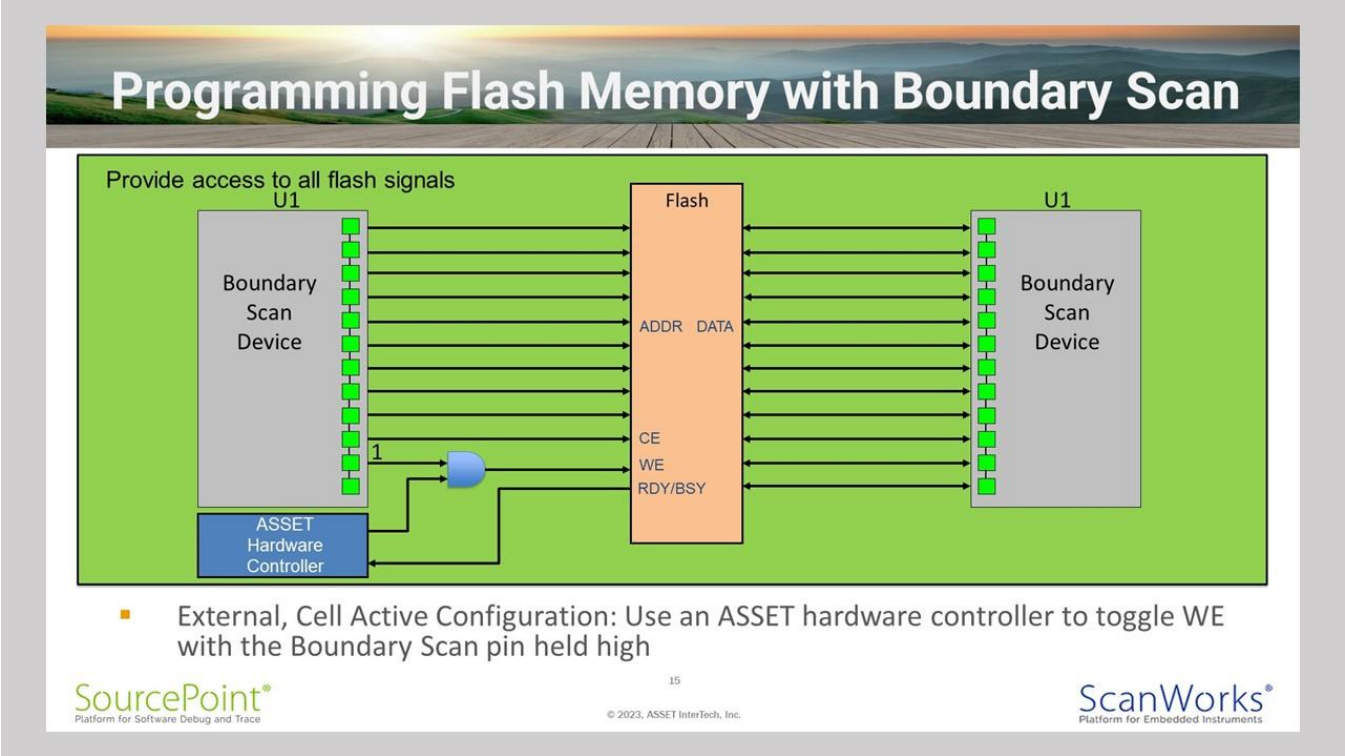

Figure 14: Programming Flash Memory with Boundary Scan – External Cell Active

For Write/Enable it takes multiple scans to toggle WE while holding the address and data steady. If we control Write/Enable with ASSET's hardware controller, the multiple scans are not necessary. We now have one scan for the address and data, then Write/Enable is toggled virtually instantaneously. This can be set up in two ways:

The first is with the External Cell Active configuration. We use the ASSET hardware controller to toggle Write/Enable with the Boundary Scan pin connected to the input of an AND gate held High.

Monitoring Ready/Busy on the ASSET Hardware controller allows ScanWorks to program the next word/byte immediately after the previous one.

Programming Flash with Boundary Scan – External Cell Z

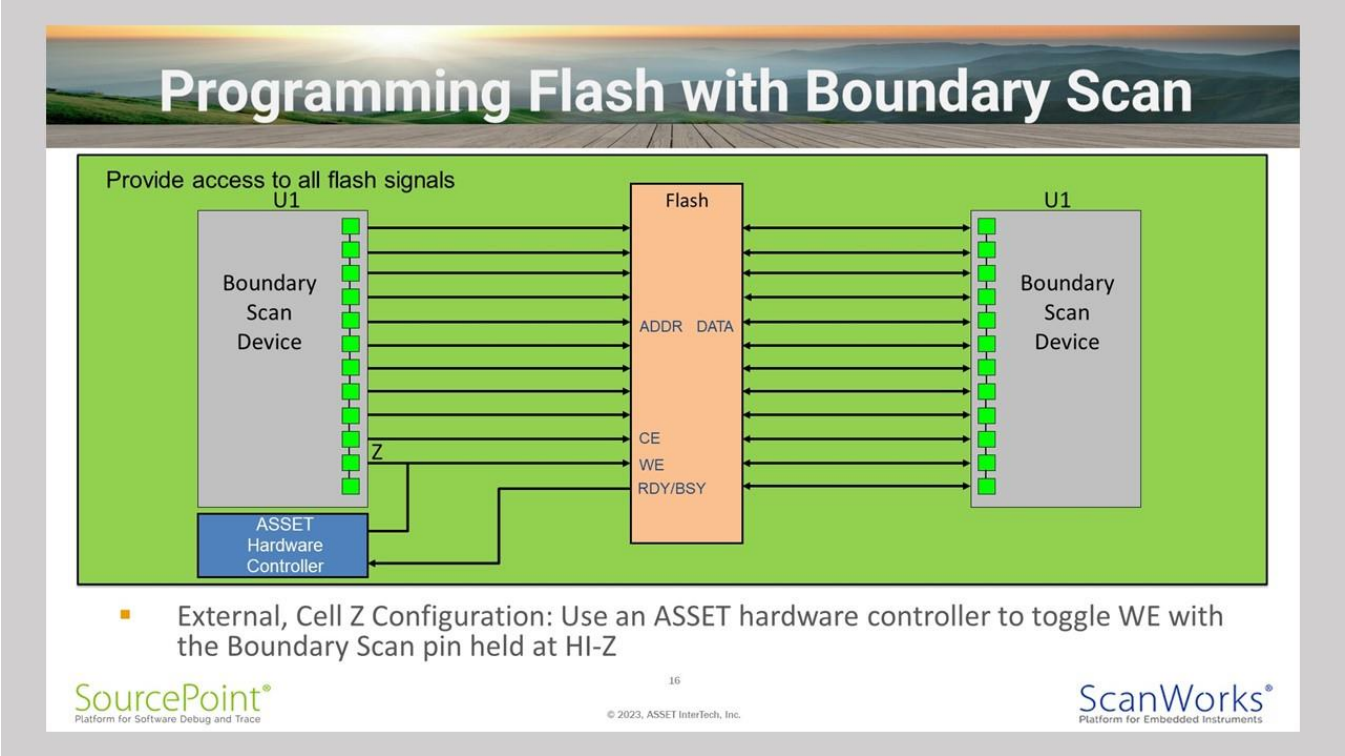

Figure 15: Programming Flash with Boundary Scan – External Cell Z

The second way is with the External Cell Z configuration. We use the ASSET Hardware controller to toggle Write/Enable with the Boundary Scan pin connected to Write/Enable held at HI-Z.

Using discrete I/O signals to control the Write Enable signal and monitor the status of the Ready/Busy can decrease flash programming time by 50% or more.

Testing FPGAs with Boundary Scan

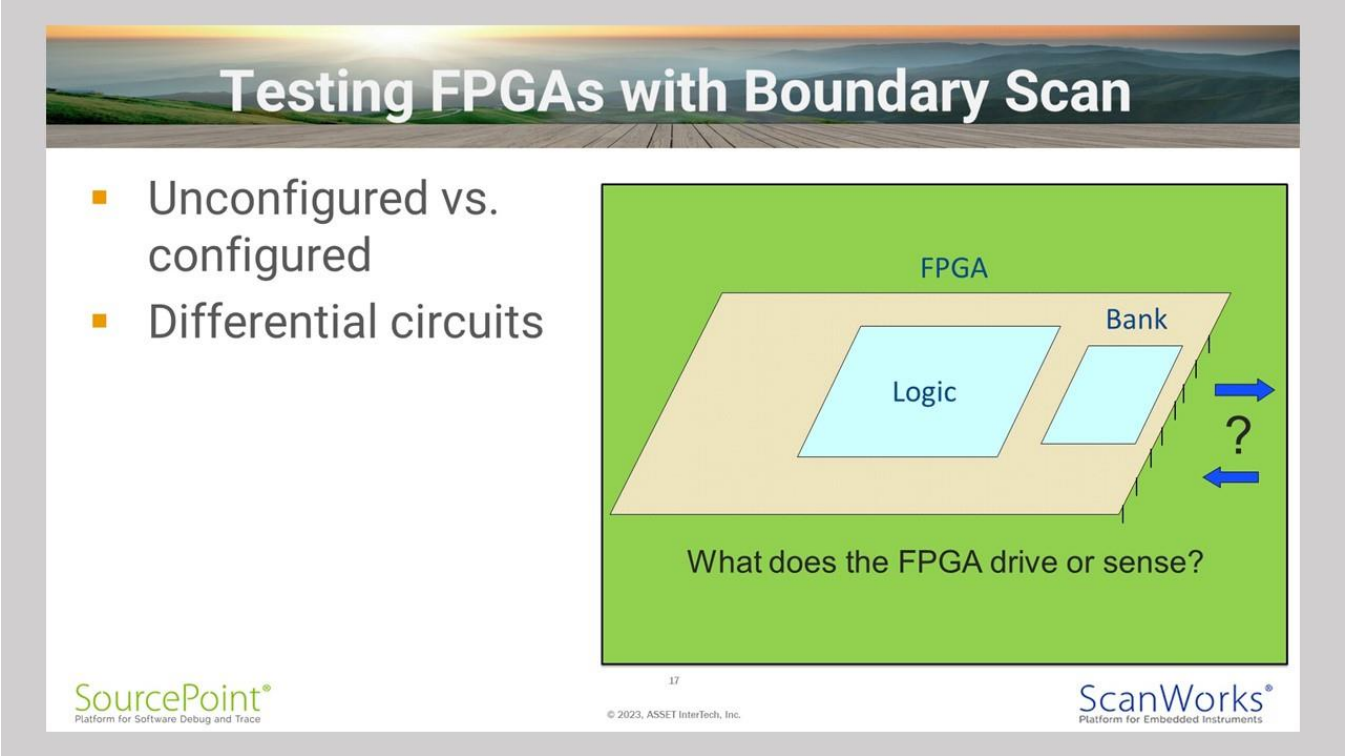

Figure 16: Testing FPGAs with Boundary Scan

FPGAs raise several test issues. Some are not strictly DFT, but they are issues that design teams should be aware of. FPGAs can be tested before or after configuration (or both). There are pros and cons to either approach which need to be considered.

Testing FPGAs with Boundary Scan – Technology Mismatch Problem

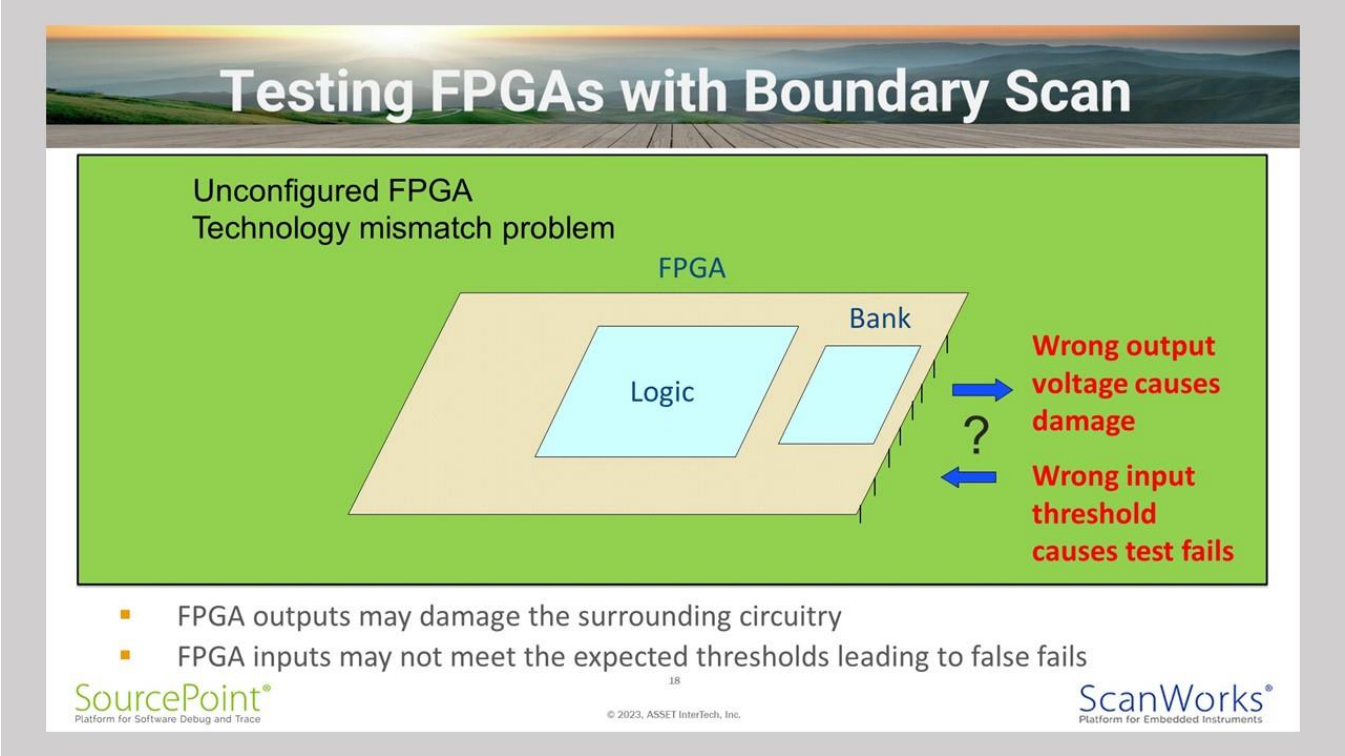

Figure 17: Testing FPGAs with Boundary Scan – Technology Mismatch Problem

In an unconfigured FPGA, the I/O details have not been programmed in yet. When we run Boundary Scan tests, we drive outputs and sense inputs. But what voltages are driven out and what technologies are we expecting to sense?

The technology mismatch problem raises two issues:

- Outputs may damage the surrounding circuitry (now in practice, we can avoid this by disabling those outputs)
- Inputs will not meet the expected thresholds, leading to false fails in our Boundary Scan tests

So, this is a clear disadvantage of testing with unconfigured FPGAs.

Testing FPGAs with Boundary Scan – Voltages

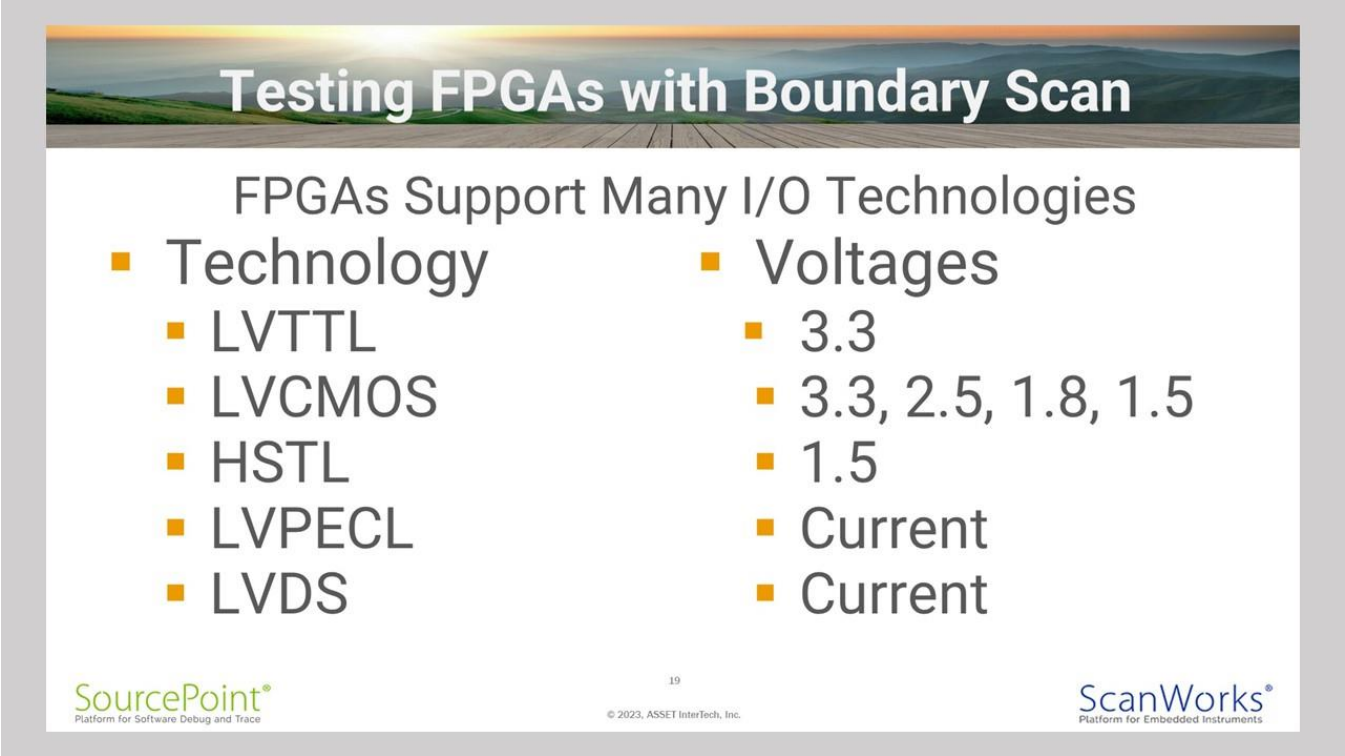

Figure 18: Testing FPGAs with Boundary Scan - Voltages

The surrounding circuitry will be expecting the technology and voltages of the configured FPGA. There are an entire range of diverse types, many are incompatible with each other.

Which voltage does the unconfigured FPGA use?

Testing FPGAs with Boundary Scan – Default Technology

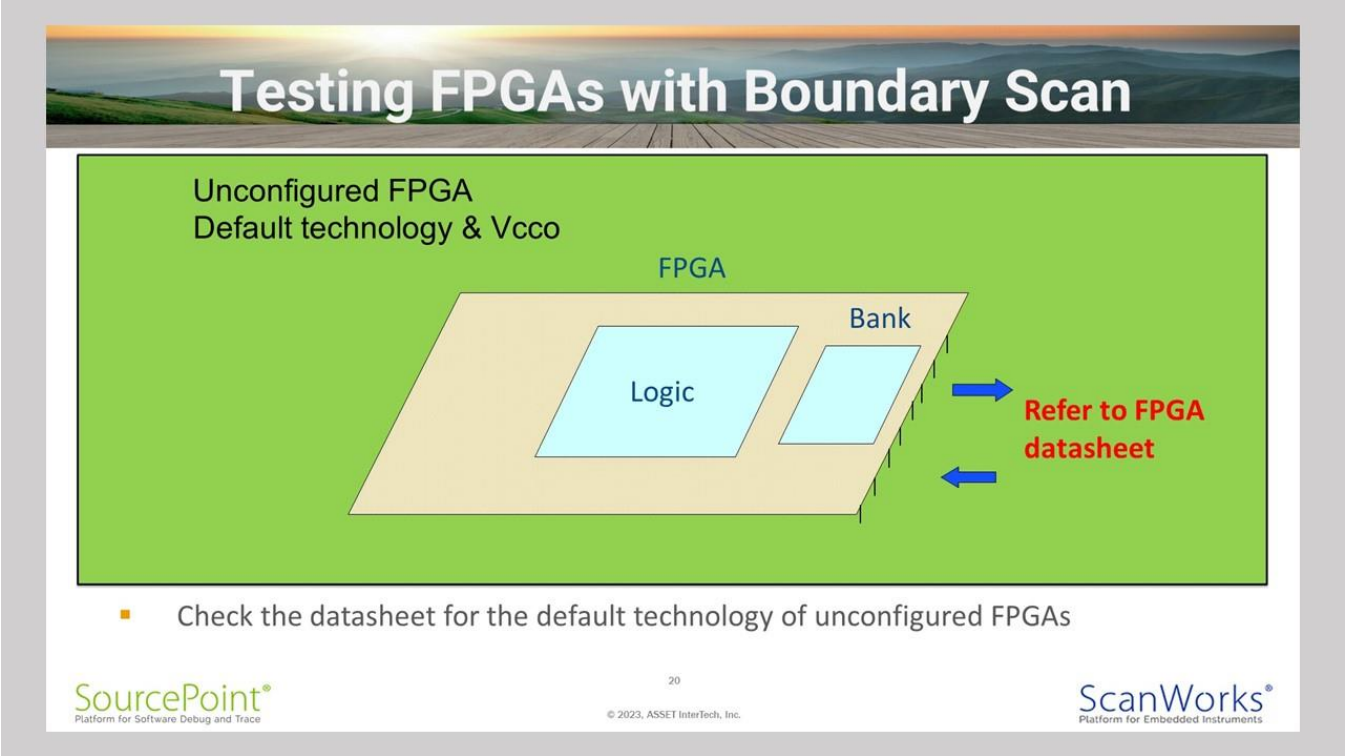

Figure 19: Testing FPGAs with Boundary Scan – Default Technology

Due to the considerable number of FPGAs on the market, check the datasheet for the default technology of your unconfigured FPGA.

Testing FPGAs with Boundary Scan – Unconfigured

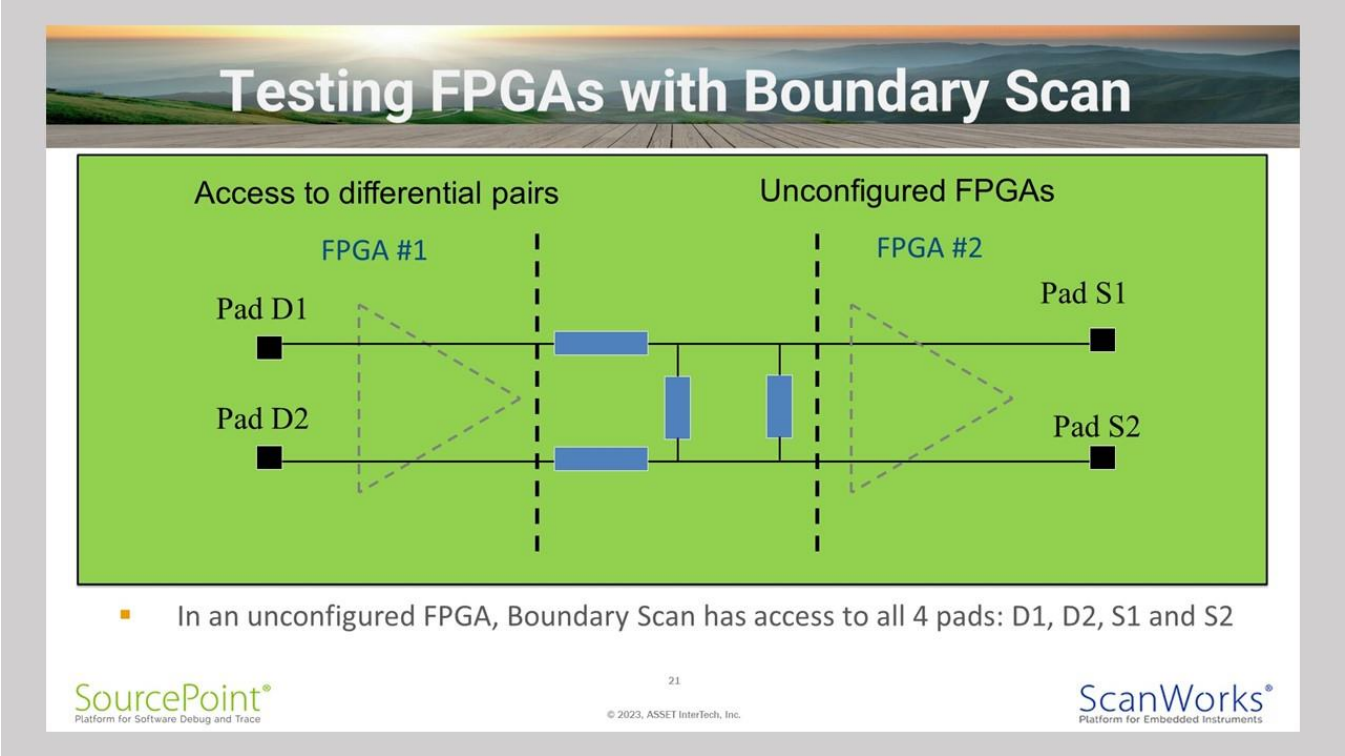

Figure 20: Testing FPGAs with Boundary Scan - Unconfigured

This diagram shows an FPGA on the left with a differential pair output. On the right is another FPGA with the input differential pair. In between are the LVDS resistor network terminating the drive and receive ends. Notice that there are two pins associated with the pair and each has its own pad on the silicon. The differential drive and receive amps are shown in outline because, in an unconfigured FPGA, they are not connected to the pair yet.

Boundary Scan has access to all 4 pads: D1, D2, S1 and S2.

The resistors are digitally transparent. We can drive patterns from D1 and sense them at D2, S1 and S2. In fact, we can drive from each pad in turn, sensing at the other 3. Thus, we can test these nets and detect and diagnose interconnect faults that could occur.

Testing FPGAs with Boundary Scan – Dangling Pair Transmitter

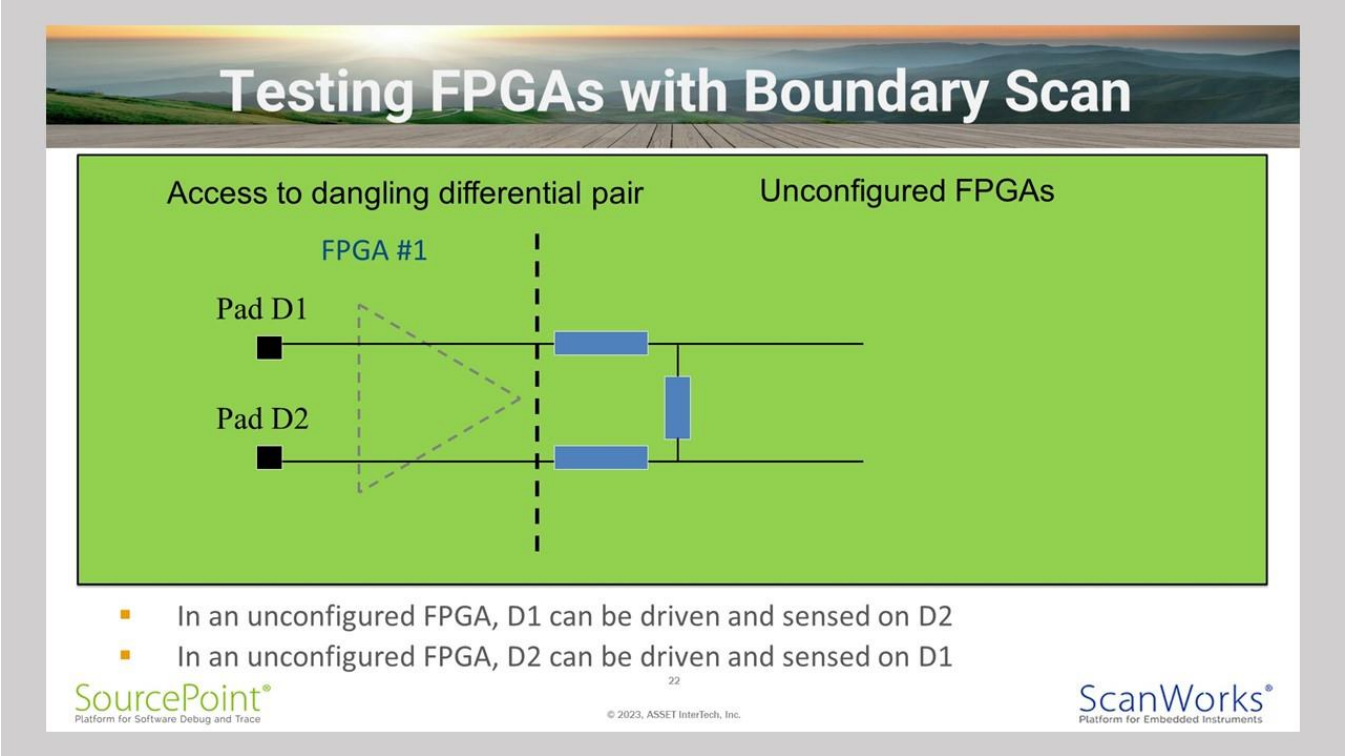

Figure 21: Testing FPGAs with Boundary Scan – Dangling Pair Transmitter

Even if we only have access to the drive end of the differential circuit, we can drive D1 and sense on D2 and vice versa. Before configuration, these are not “drive” or “sense” ends but bi-directional.

Testing FPGAs with Boundary Scan – Dangling Pair Receiver

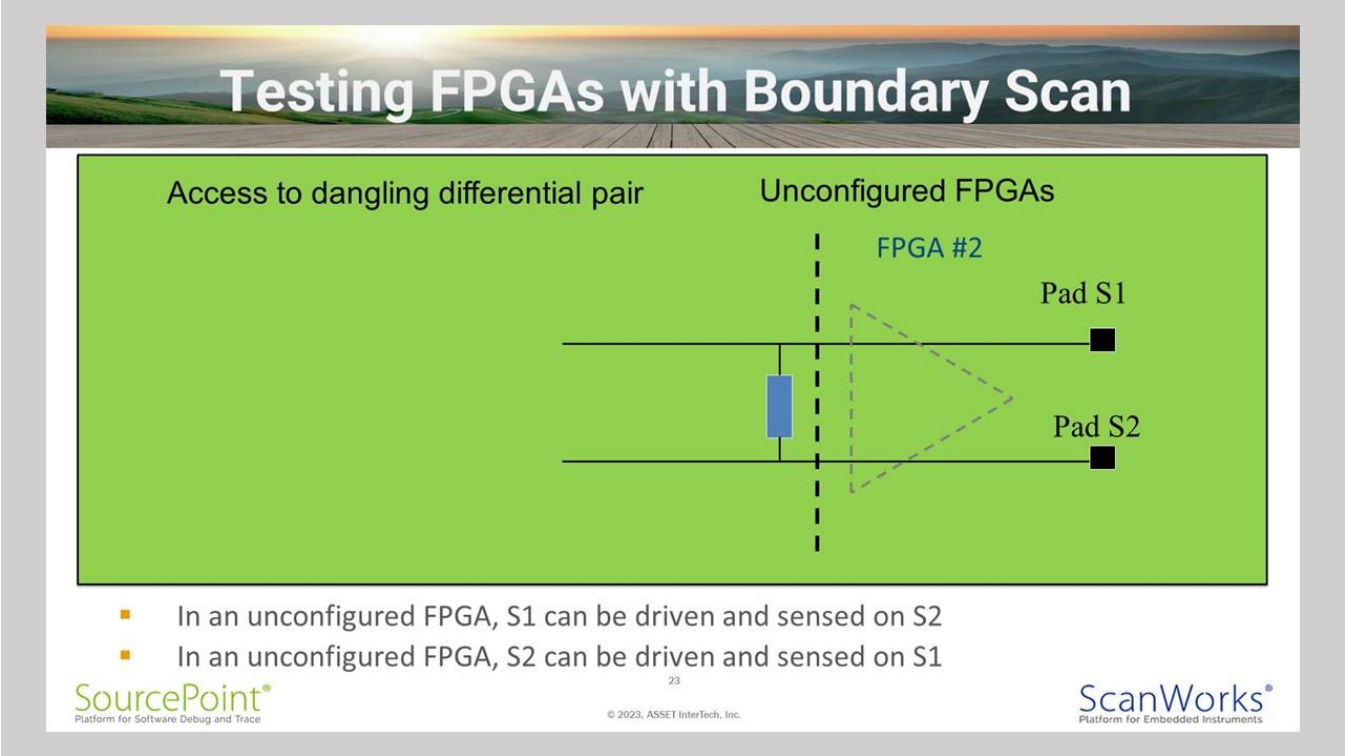

Figure 22: Testing FPGAs with Boundary Scan – Dangling Pair Receiver

The same goes for the other end of the differential pair.

Testing FPGAs with Boundary Scan – Unconfigured Considerations

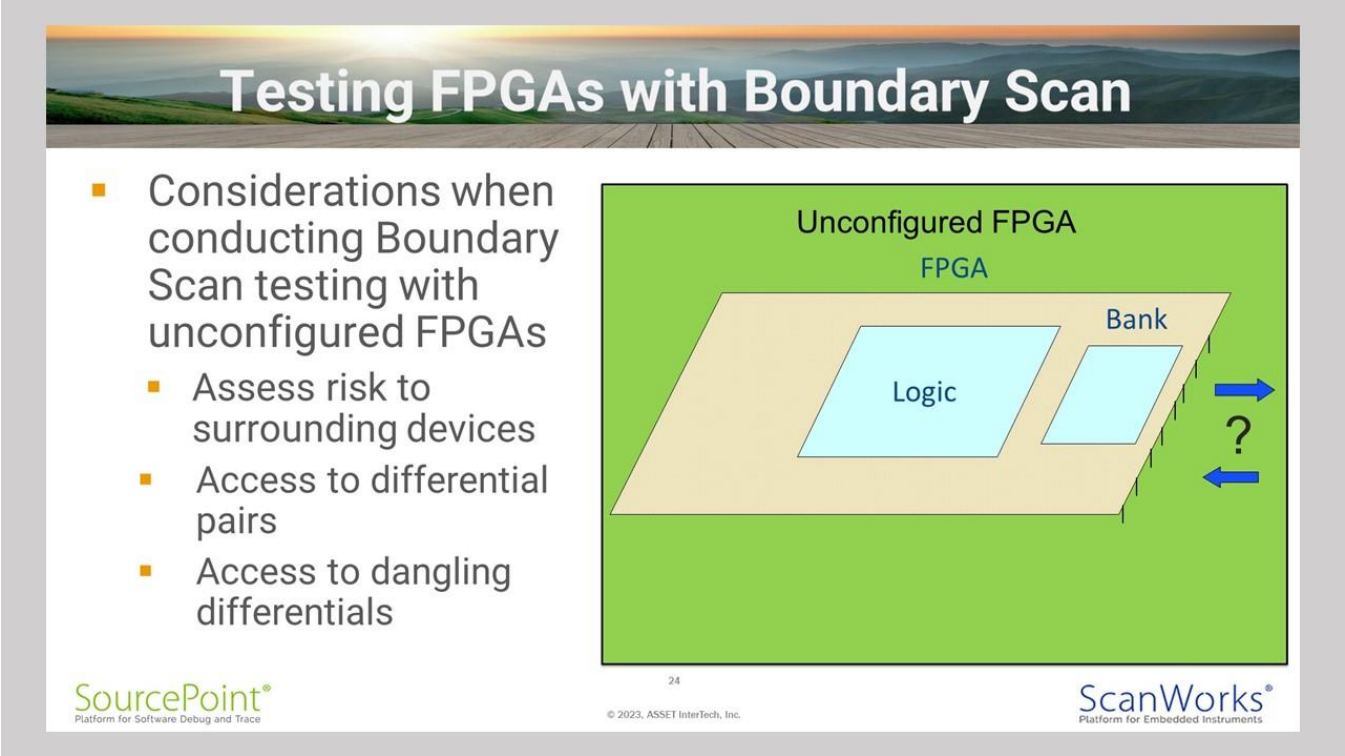

Figure 23: Testing FPGAs with Boundary Scan – Unconfigured Considerations

To summarize, the considerations you should keep in mind when conducting Boundary Scan testing with unconfigured FPGAs are that you should assess risk to surrounding devices and consider the amount of test coverage that will be available on differential signal nets.

Testing FPGAs with Boundary Scan – Configured

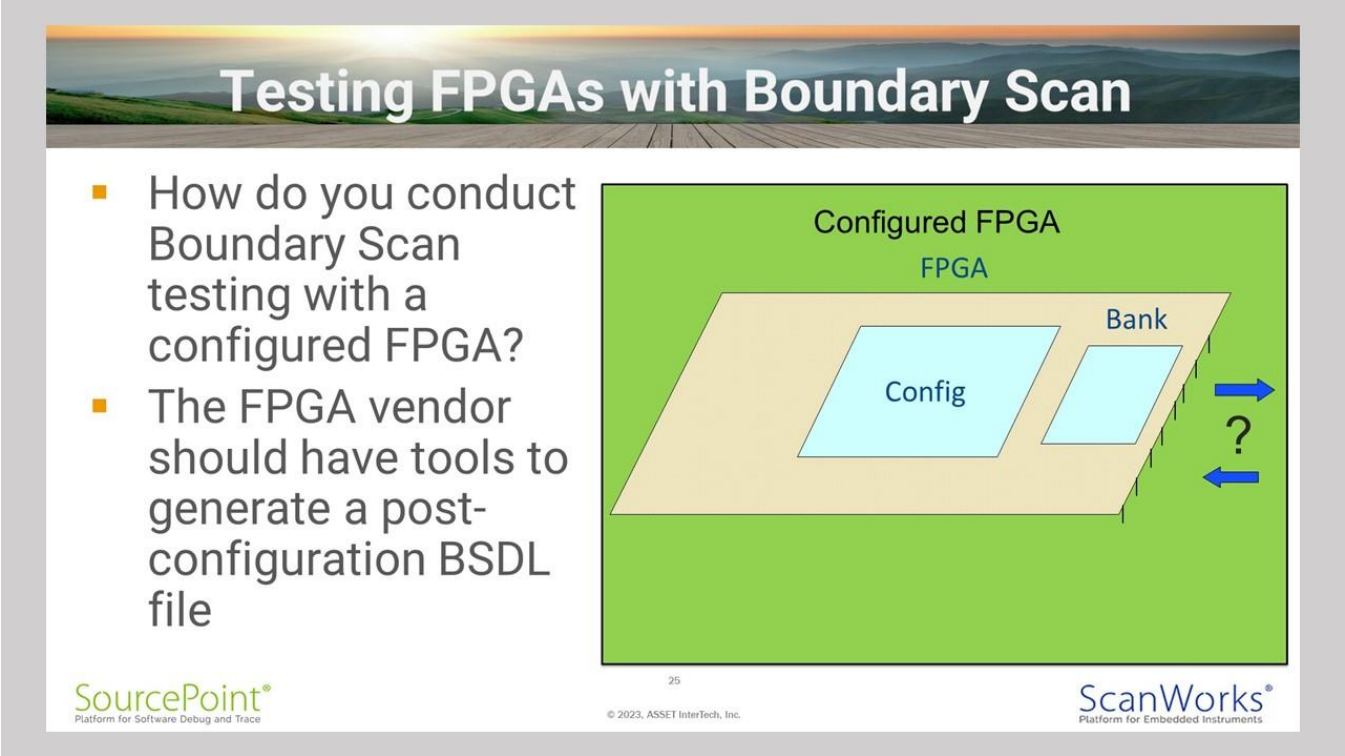

Figure 24: Testing FPGAs with Boundary Scan – Configured

Turning to the case for testing configured FPGAs. The BSDL file supplied by the device manufacturer is for the unconfigured device. Once the device is configured the BSDL needs to be modified.

The design team should provide you with the configuration file. The FPGA vendor should have tools to generate a post-configuration BSDL file leveraging the configuration file. So, the first disadvantage of testing configured FPGAs is that a custom BSDL must be created.

Testing FPGAs with Boundary Scan – Multiple Configurations

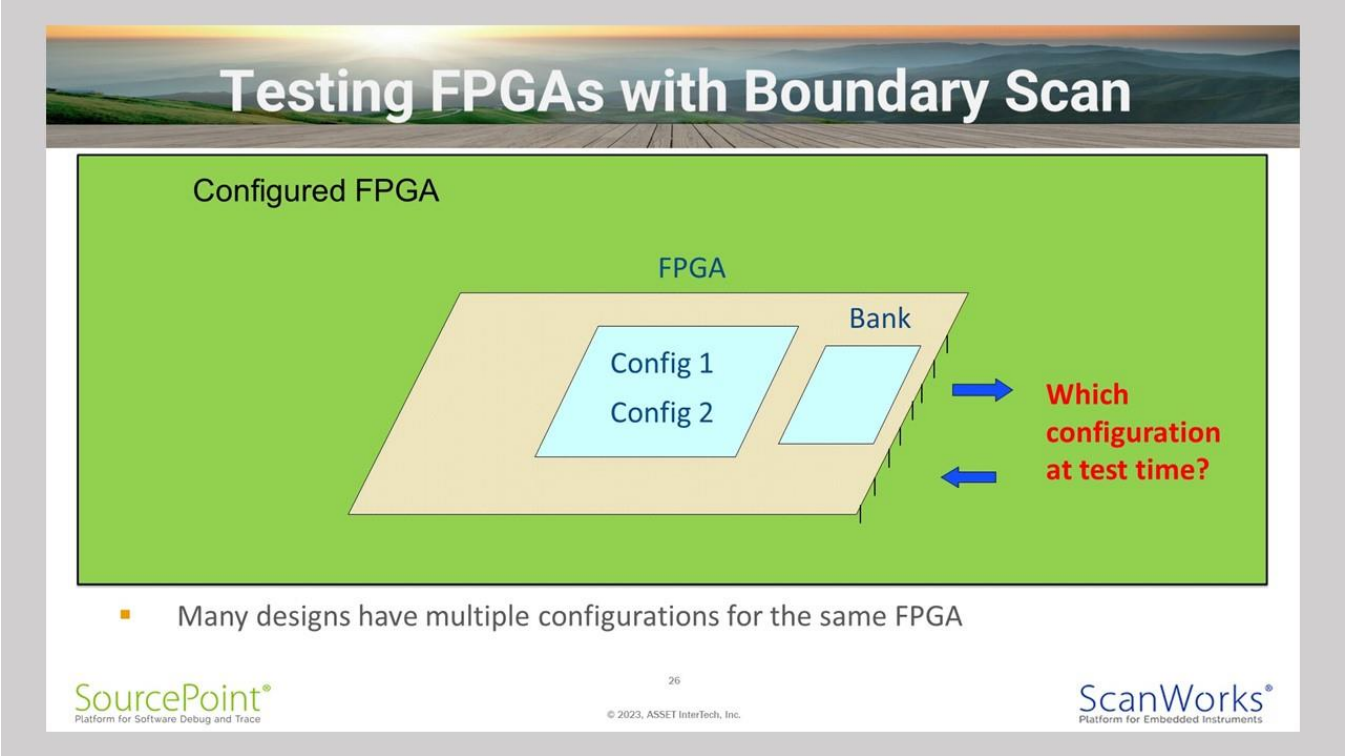

Figure 25: Testing FPGAs with Boundary Scan – Multiple Configurations

Many designs have multiple configurations for the same FPGA. Configuration details may also change from time to time (field upgrades, etc).

So, the second disadvantage of testing configured FPGAs is controlling which configuration is present in the FPGA.

Testing FPGAs with Boundary Scan – User Code

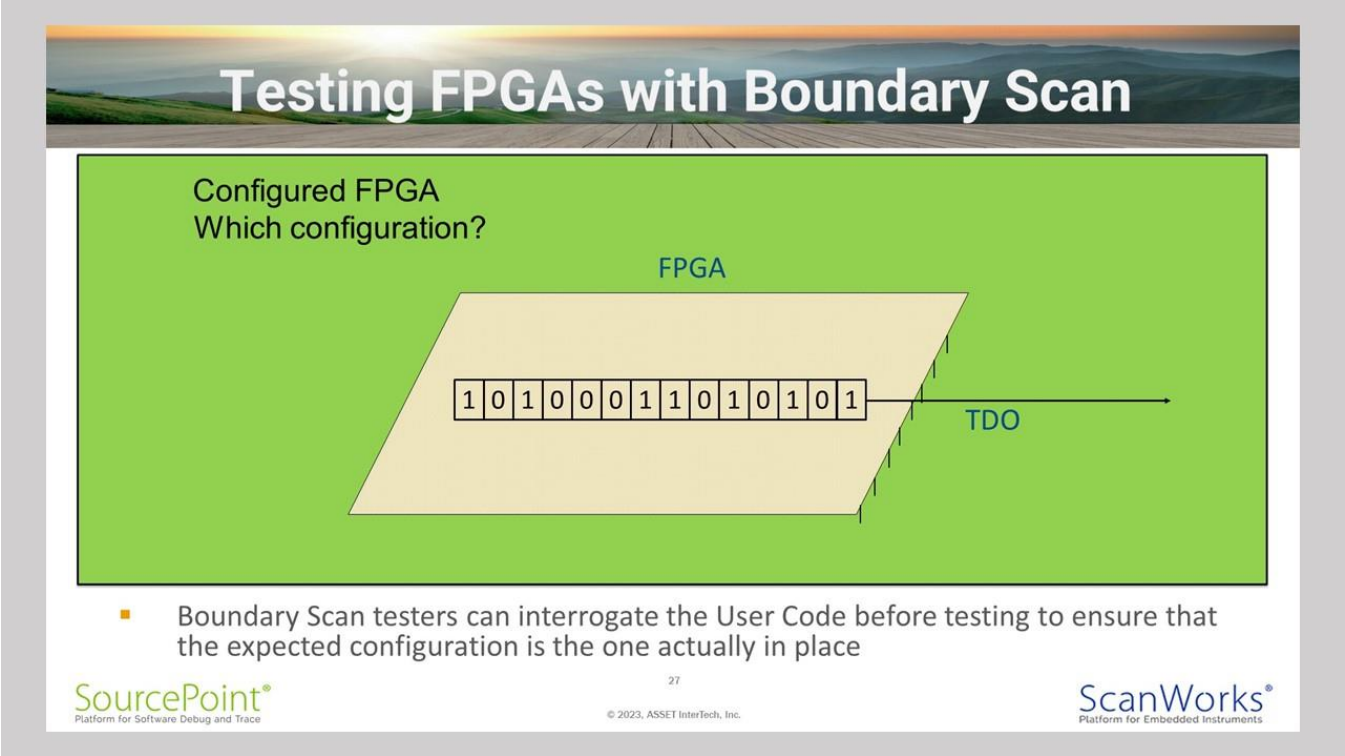

Figure 26: Testing FPGAs with Boundary Scan – User Code

Boundary Scan testers can interrogate the User Code before testing to ensure that the expected configuration is the one actually in place. User codes are like the IDCODE, but they are under your control.

User Codes should be unique for every version of every configuration. If you currently implement User Codes, you may see testing with post-configured BSDLs as an advantage.

Testing FPGAs with Boundary Scan – Configured Driver and Receiver

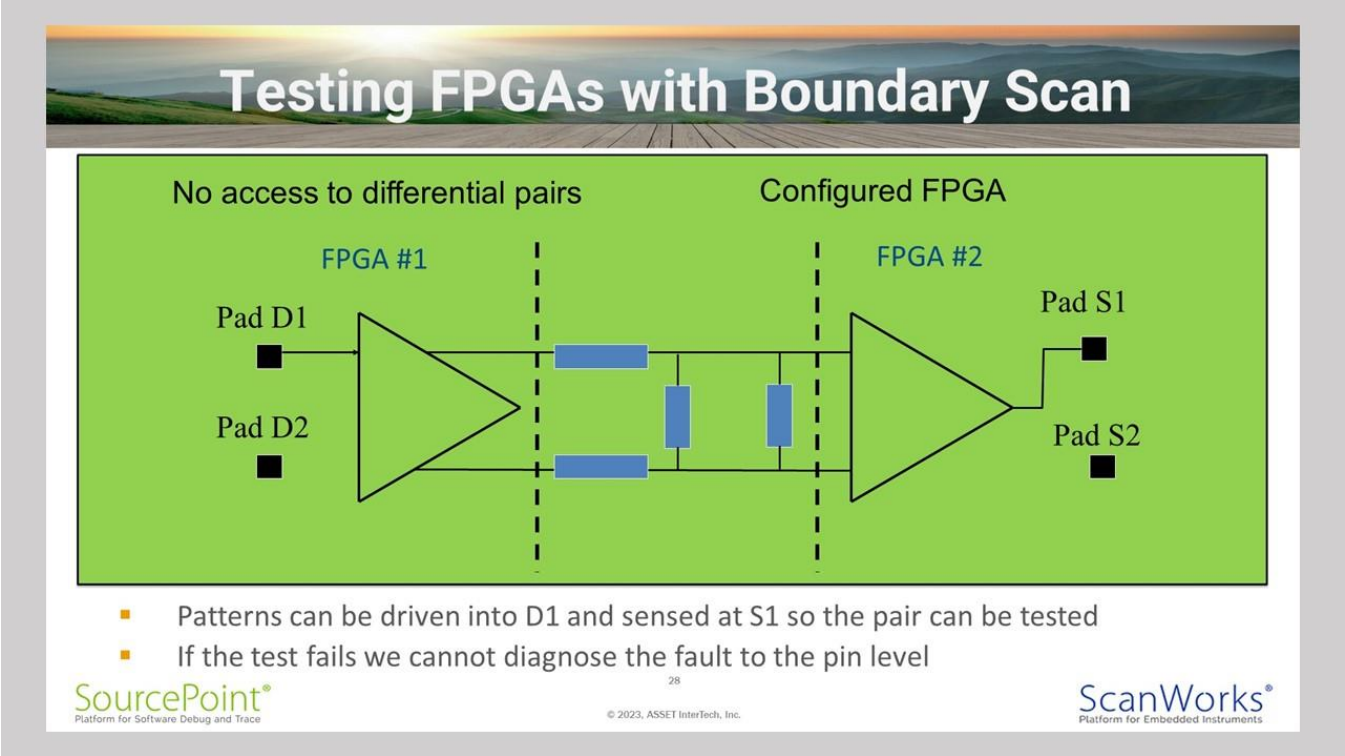

Figure 27: Testing FPGAs with Boundary Scan – Configured Driver and Receiver

This is a differential pair after configuration. Notice that the drive and sense amplifiers are now in place. These sit between the pads that Boundary Scan accesses and the pins. Notice that D2 and S2 are no longer connected to anything. We can drive patterns into D1 and sense them at S1 so we can test the pair.

But, if the test fails, we cannot diagnose the fault to the pin level. We would not know whether to rework FPGA #1 or FPGA #2.

Testing FPGAs with Boundary Scan – Dangling Differential Driver

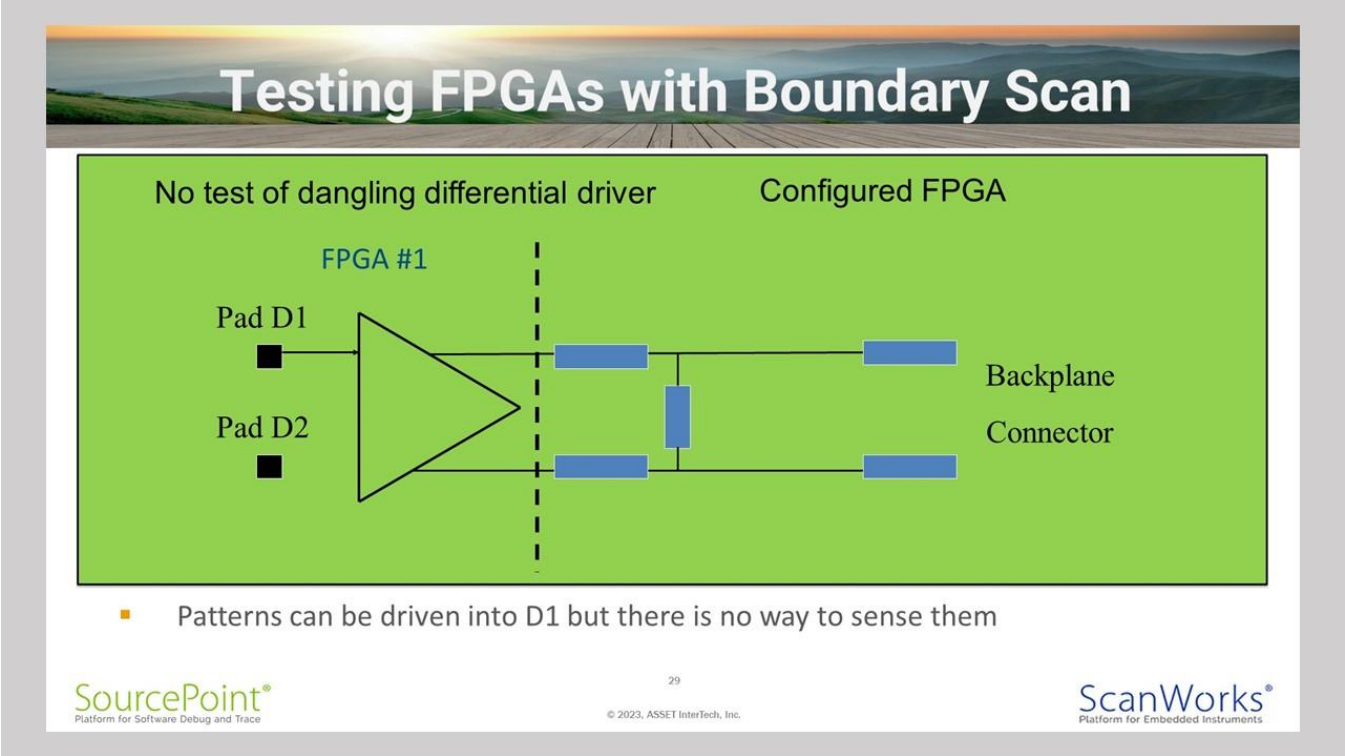

Figure 28: Testing FPGAs with Boundary Scan – Dangling Differential Driver

If we only have access to one end of the pair, we cannot test it at all. Patterns can be driven into D1, but we have no way to sense them.

Testing FPGAs with Boundary Scan – Dangling Differential Receiver

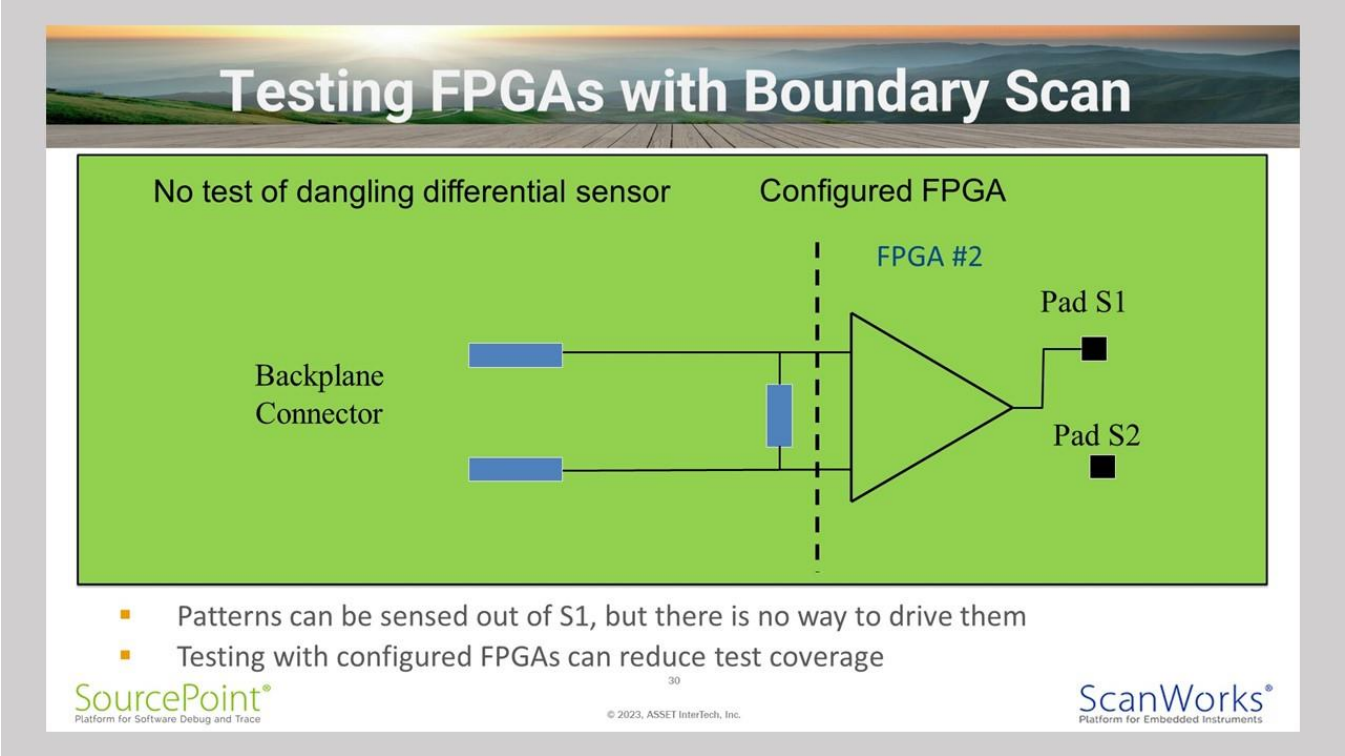

Figure 29: Testing FPGAs with Boundary Scan – Dangling Differential Receiver

The same is true at the sense end. We could sense patterns out of S1, but we have no way to drive them. Testing with configured FPGAs can reduce test coverage.

Testing FPGAs with Boundary Scan – Configured Considerations

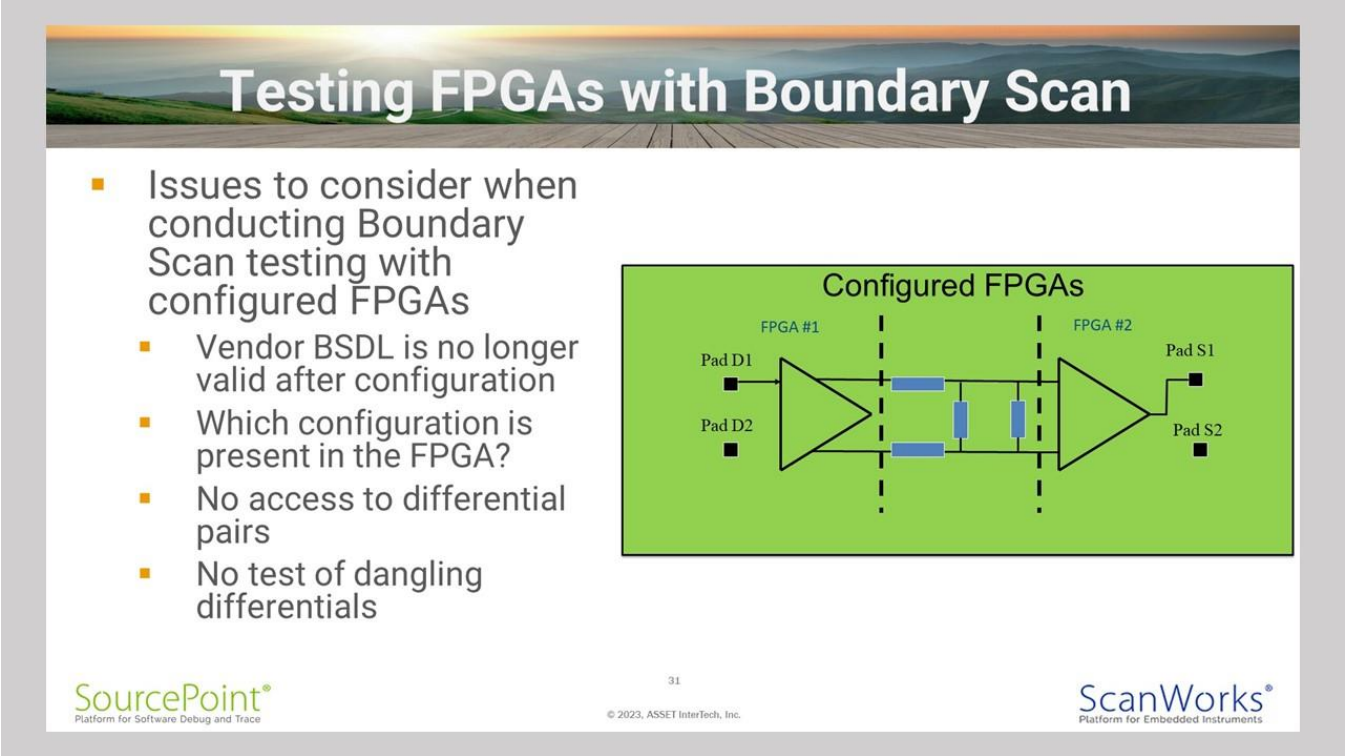

Figure 30: Testing FPGAs with Boundary Scan – Configured Considerations

To summarize these are the issues to consider when testing with configured FPGAs.

Testing FPGAs with Boundary Scan – Configured vs Unconfigured Summary

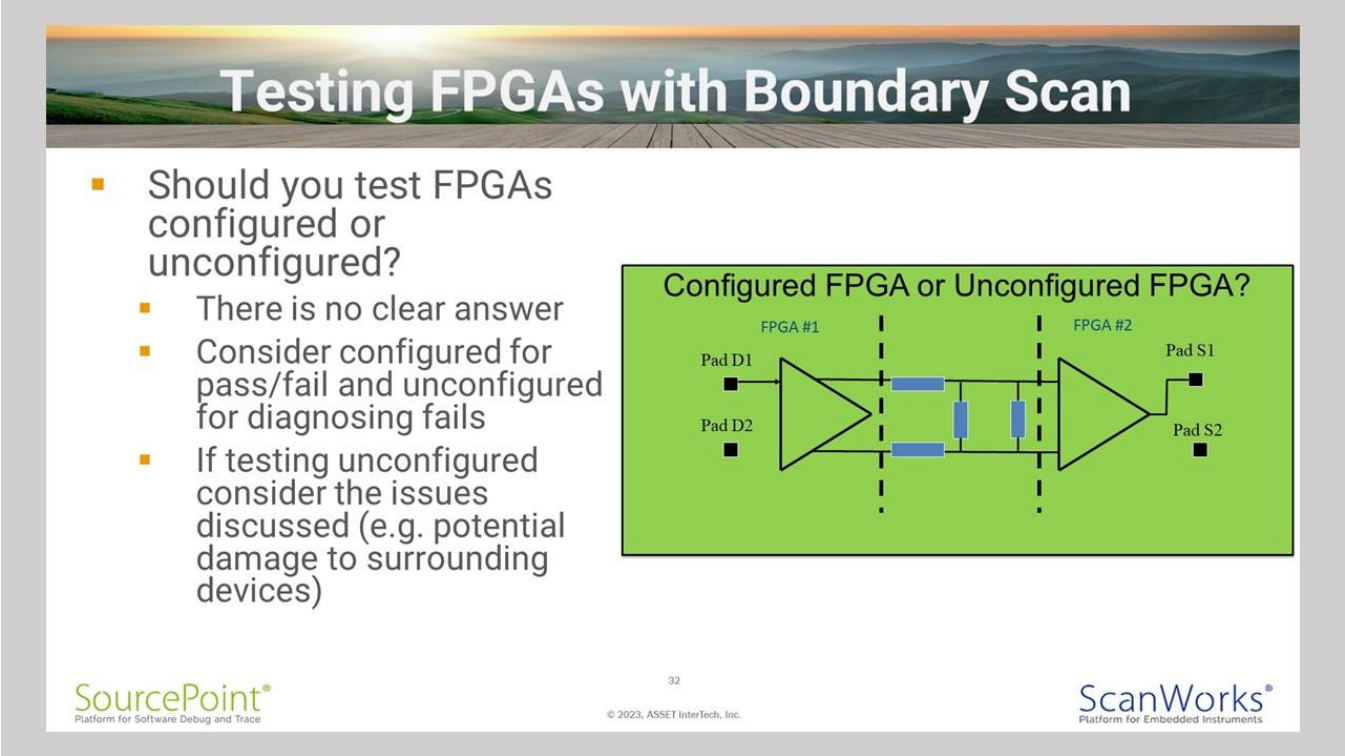

Figure 31: Testing FPGAs with Boundary Scan – Configured or Unconfigured Summary

So, should you test FPGAs configured or unconfigured? There is no clear answer, it depends on your circumstances. Testing configured is probably the safest strategy to reduce possible damage to surrounding devices. Testing configured might also be necessary to validate interconnects for low-voltage memories.

Testing unconfigured is probably best if you use differential circuits or if configuration versions are difficult to predict (e.g., field test/returns).

Summary of Board DFT based on Boundary Scan – Volume 2

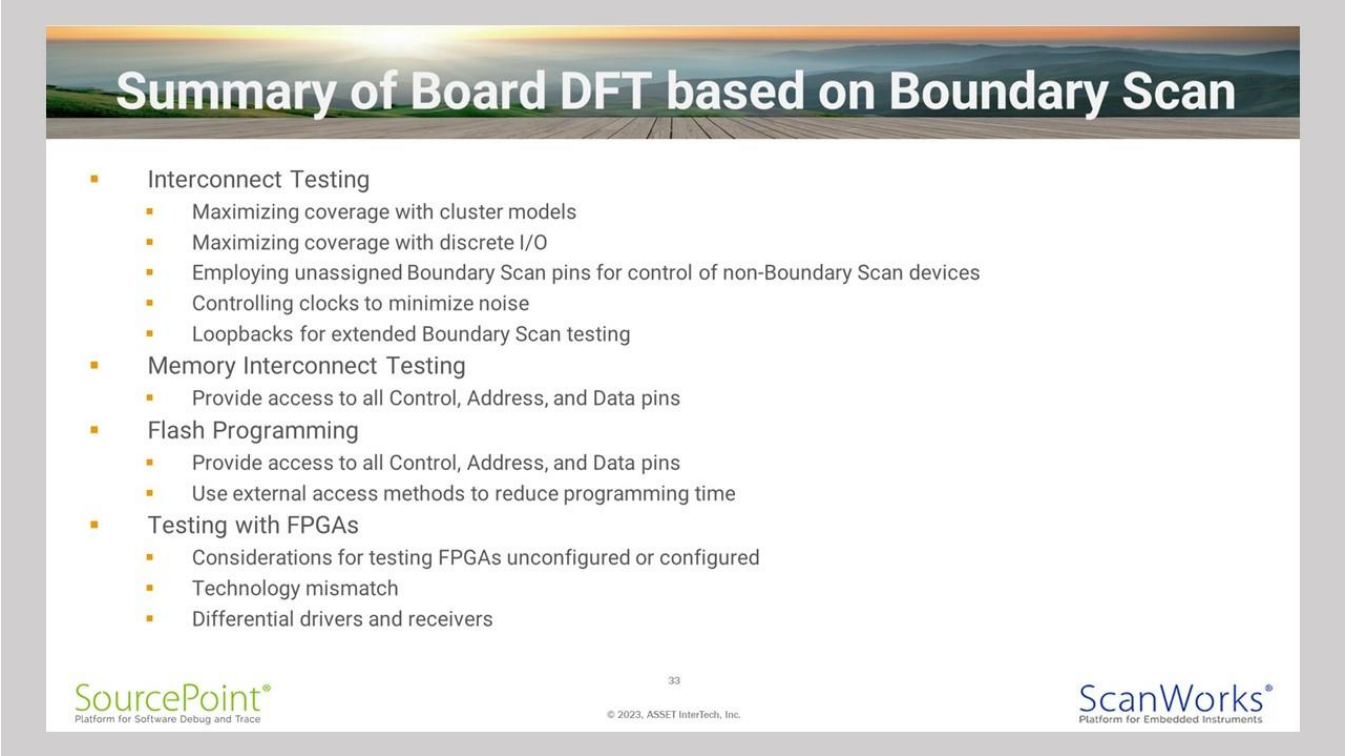

Figure 32: Summary of Board DFT based on Boundary Scan – Volume 2

So, in summary. These are the DFT guidelines we've covered today.

Conclusion

In this eBook, we examined Design for Test (DFT) guidelines specific to the design of boards to be tested through the Boundary Scan registers of IEEE 1149.1-compliant devices. Boards designed implementing Boundary Scan DFT guidelines are capable of being tested during the manufacturing process with a Boundary Scan test tool. The most important guideline (presented in volume 1 of this eBook) is that where possible, use 1149.1-compliant devices on the board in lieu of non-Boundary Scan devices. Without Boundary Scan devices on the board, no degree of Boundary Scan coverage exists. Next, to ensure testability through the Boundary Scan registers, the 1149.1-compliant devices must be connected TDI-to-TDO. The other device TAP signals, TMS, TCK, and TRST* (if applicable) are also connected in a distributed fashion. This configuration of the 1149.1-compliant devices is known as a scan chain. Boundary Scan DFT guidelines state that access to the TAP signals be provided to the Boundary Scan test tool. The more Boundary Scan registers that are accessible on the board, the higher the Boundary Scan test coverage for detection of open and/or short structural faults.

As Boundary Scan technology matured, it is now used for testing memory devices such as SRAM and DDR, programming flash devices, and configuration of programmable devices such as FPGAs. There are also DFT guidelines that decrease the programming time of flash devices via Boundary Scan by using external hardware to access the WE RDY/BSY signals. With proper DFT access to these signals, programming time can be decreased by upwards of 50%.

When testing with FPGAs, the Test Engineer must consider if testing with the FPGA configured or unconfigured with satisfy all test requirements. Testing the FPGA unconfigured allows more test coverage because Boundary Scan has access to all IO. However, testing my damage the surrounding devices. If the FPGA is tested configured, the surrounding devices are safer, because the voltages match, however there is some loss of test coverage.

Maximizing board test coverage is imperative to improving manufacturing yields, increasing product quality, and reducing product returns. The prime reasons for developing a board test strategy are to find defects, diagnose the cause of the faults, and repair them quickly. The obtained fault data can be used to improve the processes that produced the board and alleviate conditions which create board faults.